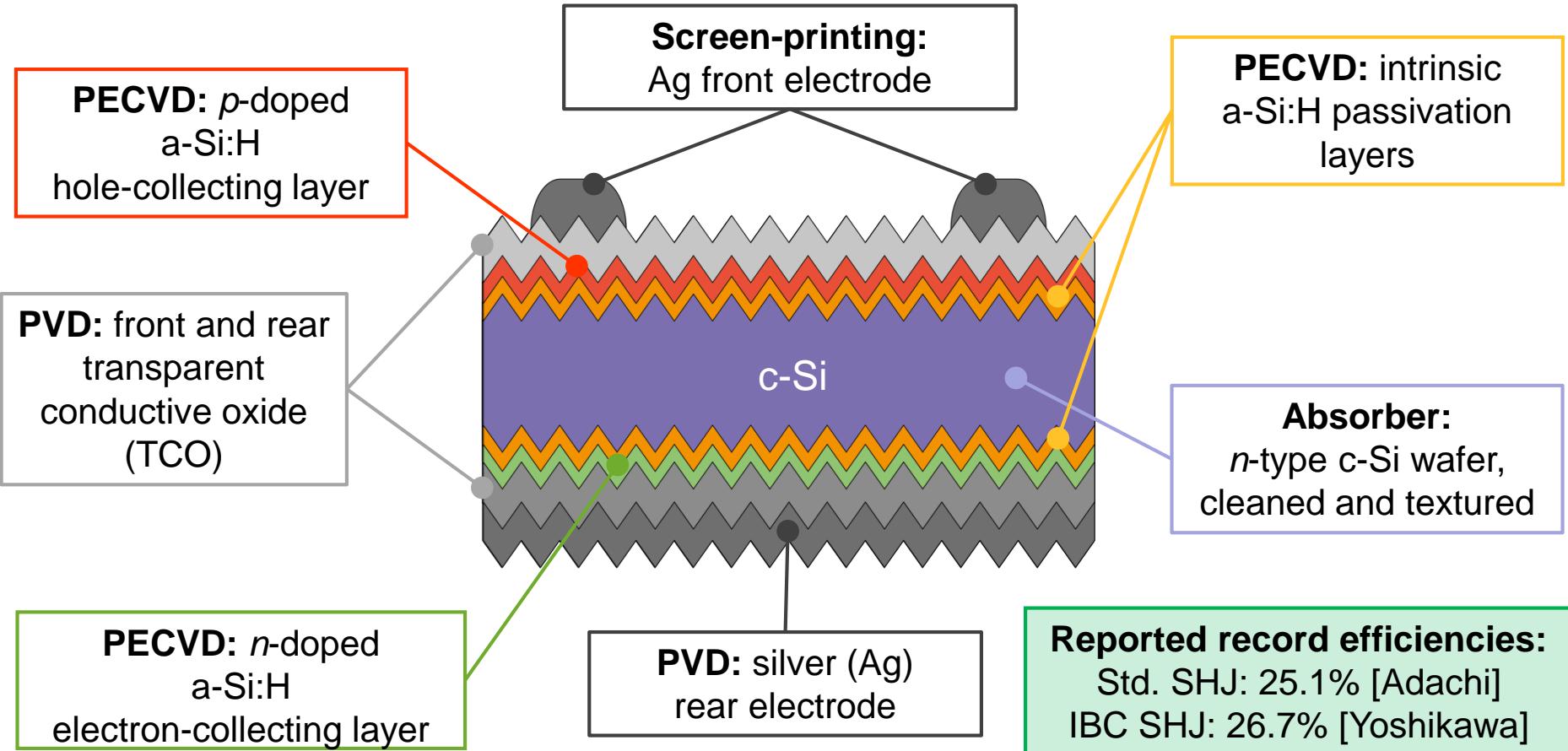


# WINDOW LAYERS FOR SILICON HETEROJUNCTION SOLAR CELLS: *Properties and Impact on Device Performance*

Johannes P. Seif

# Silicon Heterojunction Solar Cells



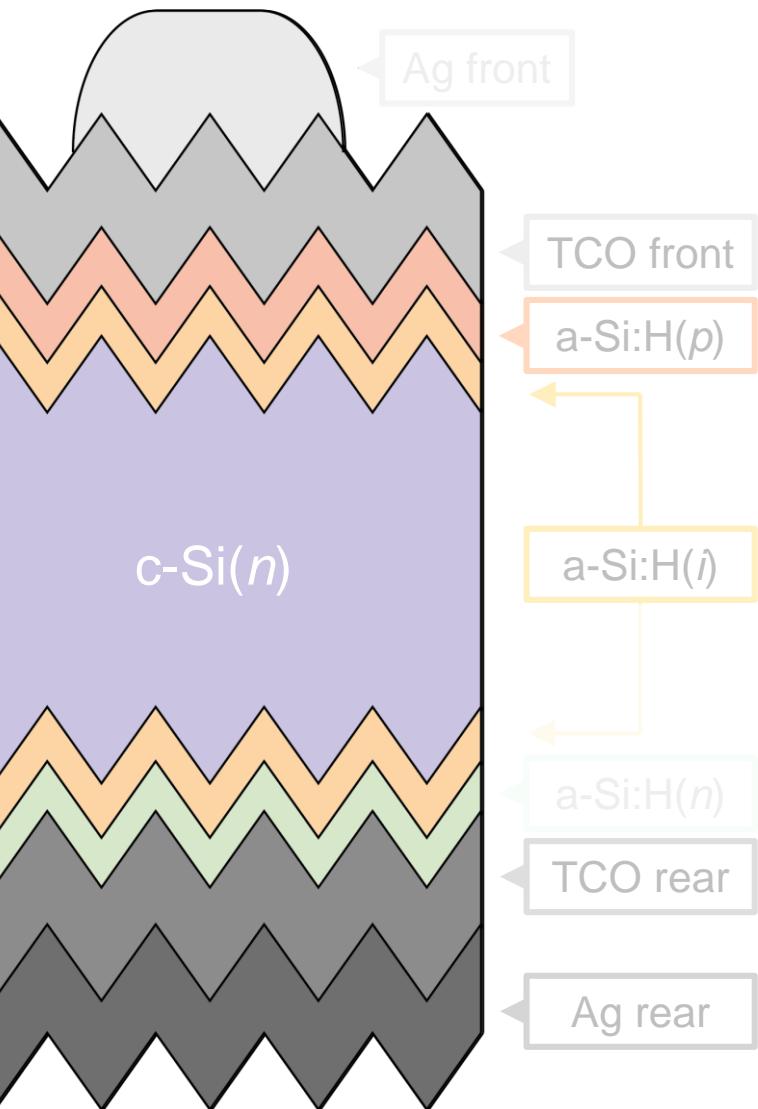
Physical Vapor Deposition / Sputtering (PVD)

Plasma Enhanced Chemical Vapor Deposition (PECVD)

D. Adachi et al., APL, 2015, 107, 233506.

K. Yoshikawa, Nature Energy, 2017, 2(5), 17032.

# Challenges: optical losses



**Parasitic absorption in the front layers:**  
generation of charge carriers that recombine before being collected.

**-2.1 mA/cm<sup>2</sup>**

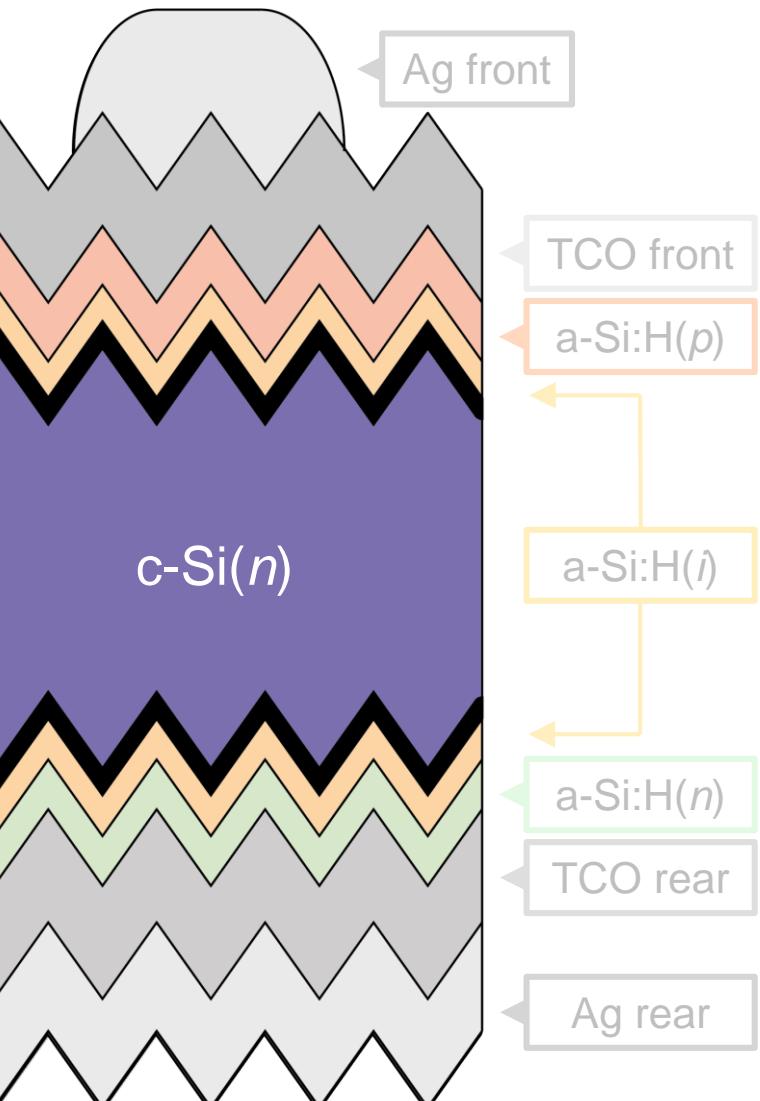
**Lower** current output of the device, *i.e.* reduced **short-circuit current density ( $J_{sc}$ )**



**-0.5 mA/cm<sup>2</sup>**

**Free-carrier absorption** in the highly doped TCO layer & **plasmonic losses** in the metal rear reflector.

# Challenges: electrical losses

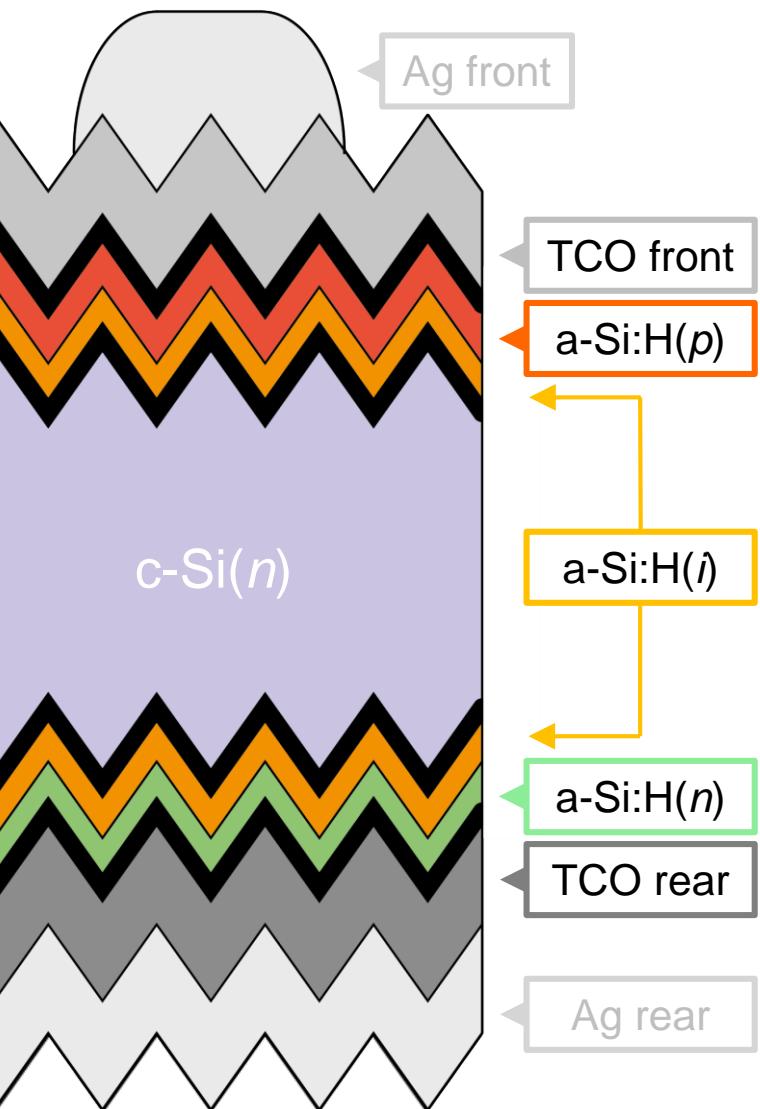


## Recombination

- Radiative
- Auger
- Via defect states in the bulk or at the surface

**Lowers** the maximal attainable voltage, *i.e.* the **open-circuit voltage ( $V_{oc}$ )** and **limits** the voltage at the maximum power point (fill factor, *FF*)

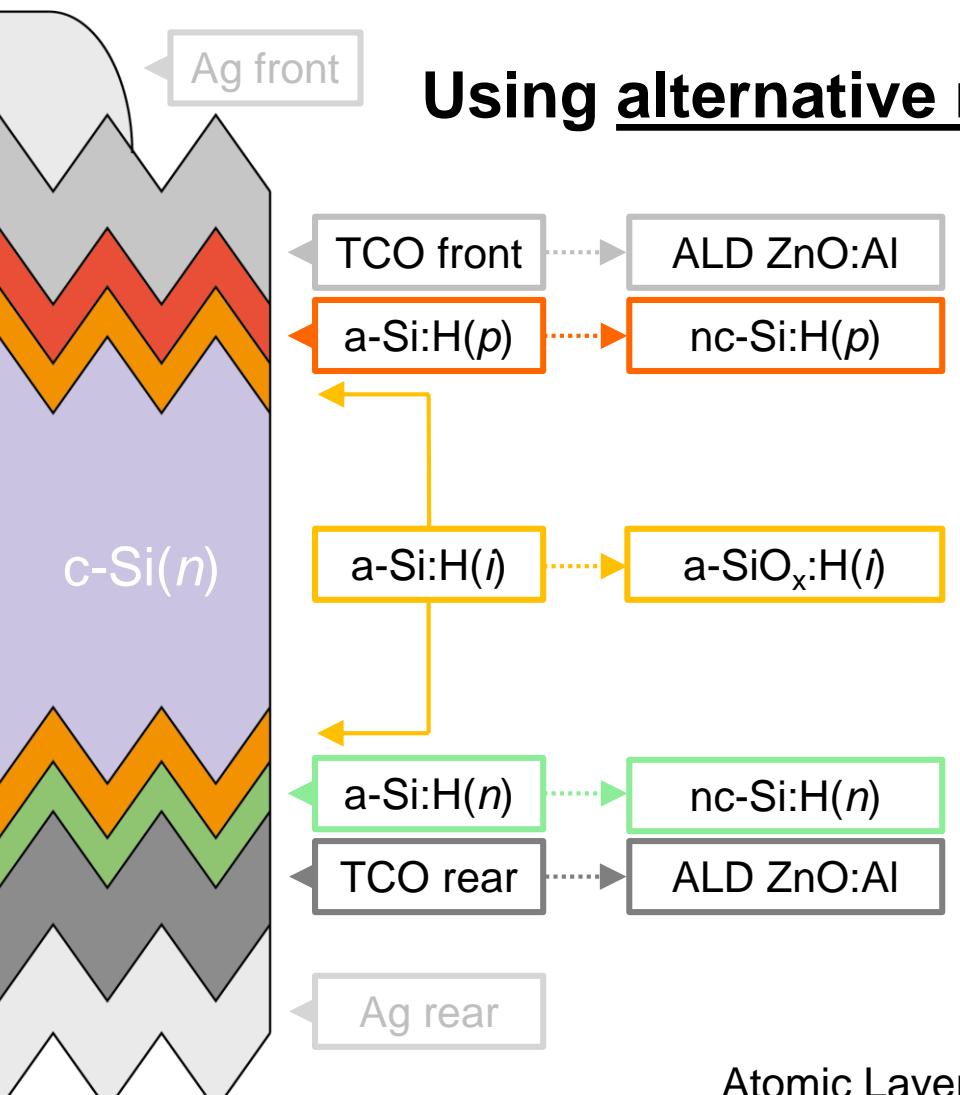
# Challenges: electrical losses



**The Transparent Conductive Oxide (TCO)** can have an influence on the a-Si:H layers (Schottky barriers) and the a-Si:H/c-Si interface (increased recombination).

**Lowers** the maximal attainable voltage, *i.e.* the **open-circuit voltage ( $V_{oc}$ )** and **limits** the voltage at the maximum power point (fill factor,  $FF$ )

# Motivation

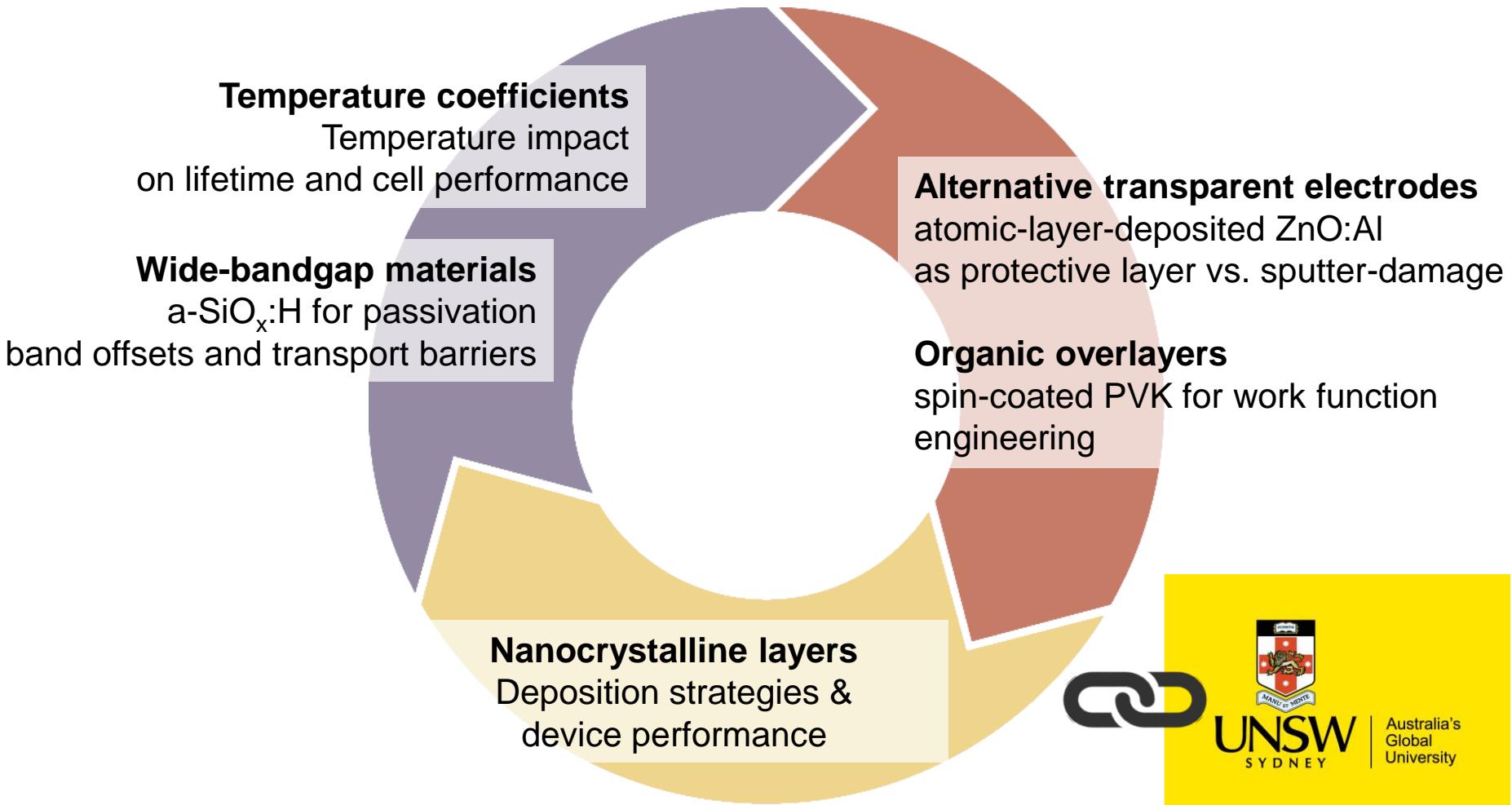


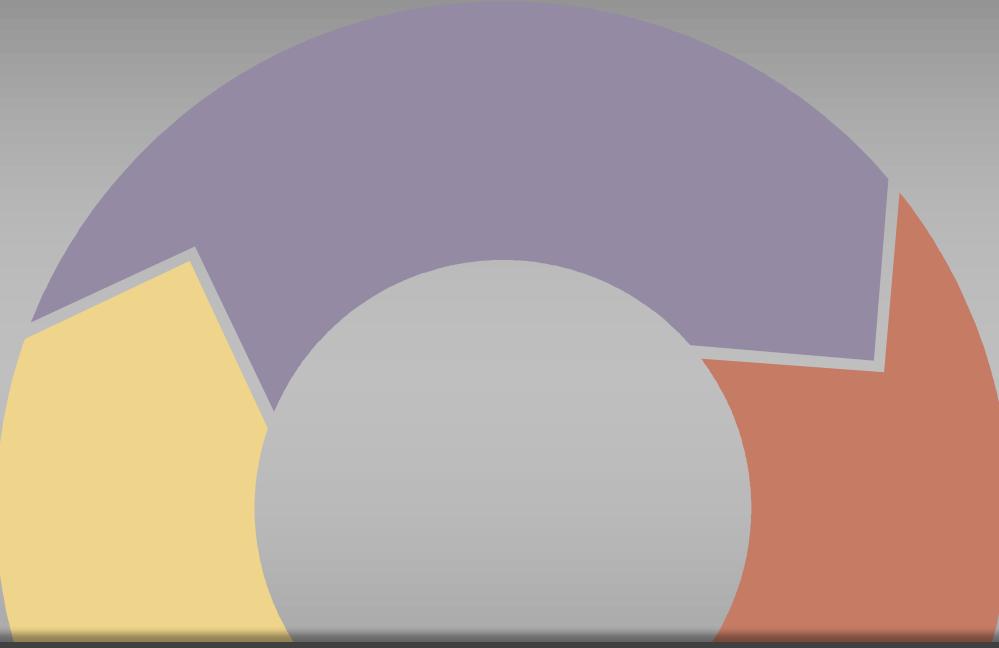
## Using alternative materials to mitigate losses

### Goals

- Development of PECVD processes for a-SiO<sub>x</sub>:H and nc-Si:H
- Understand their impact (*material properties and processing*) on device performance ( $J_{sc}$ ,  $V_{oc}$ ,  $FF$ )
- Reduction of optical and electrical losses

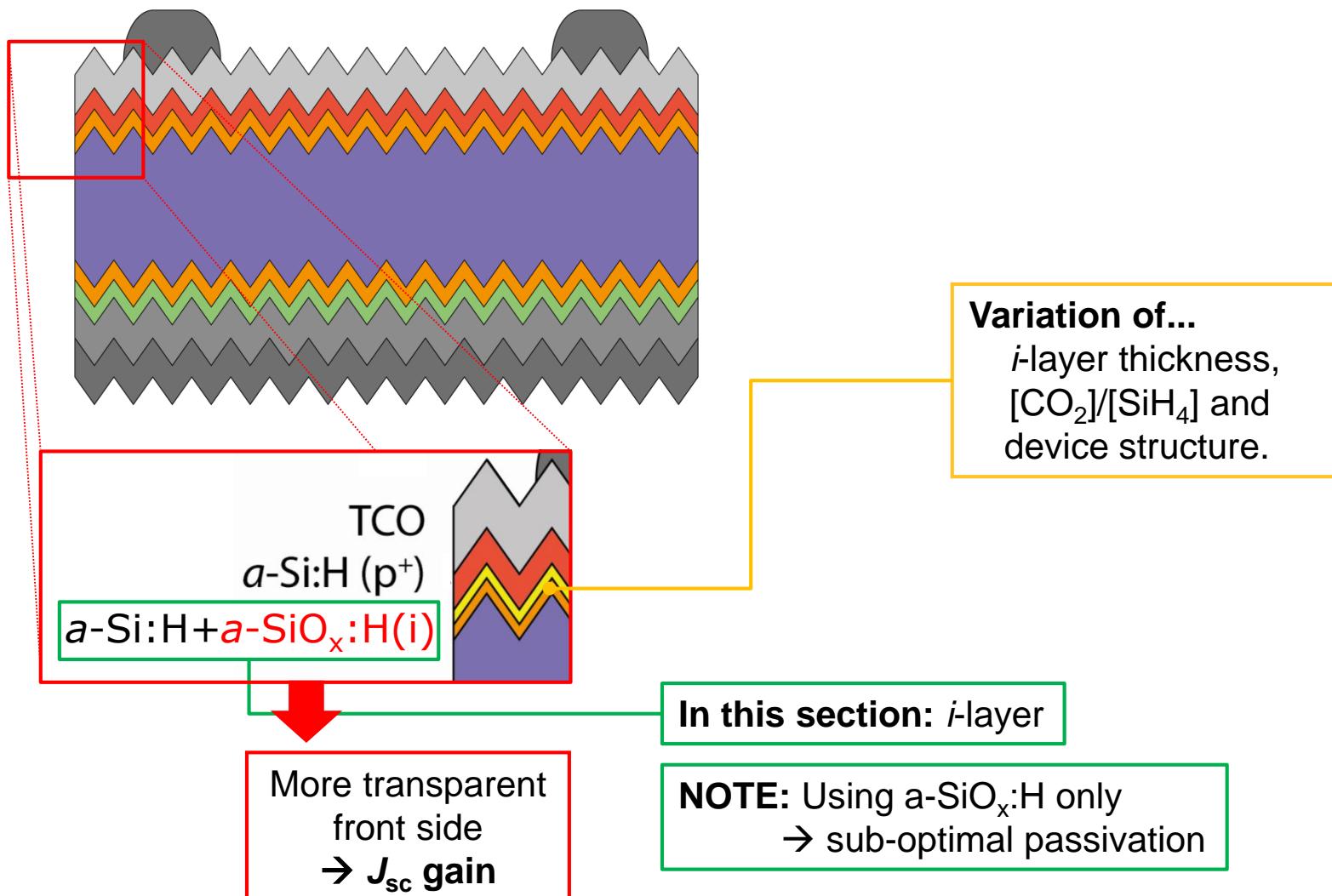
# Outline



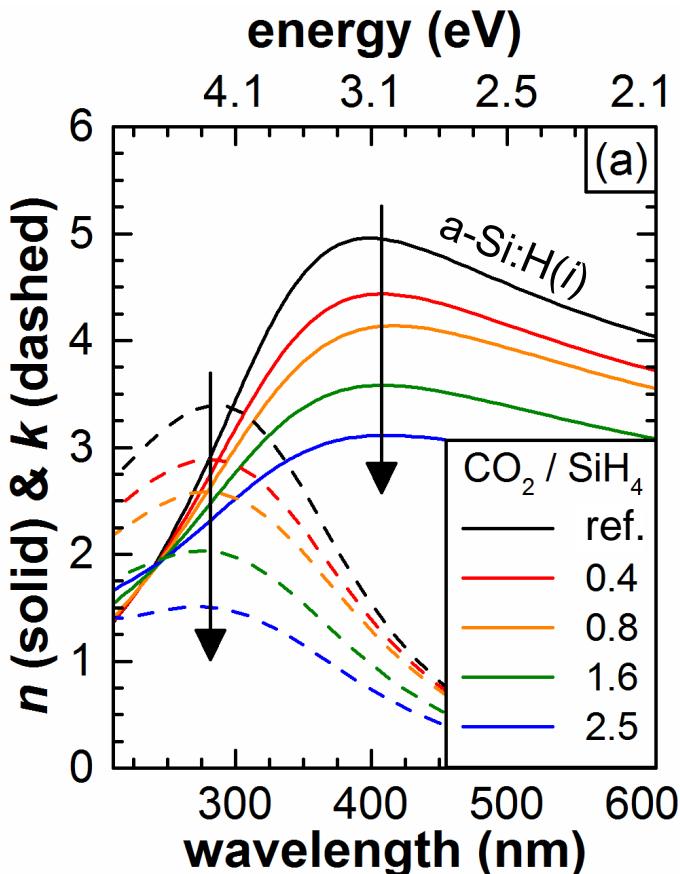


## Wide-bandgap materials: *a-SiO<sub>x</sub>:H – optical gain versus transport*

# Motivation



# a-SiO<sub>x</sub>:H: optical properties



From spectroscopic ellipsometry

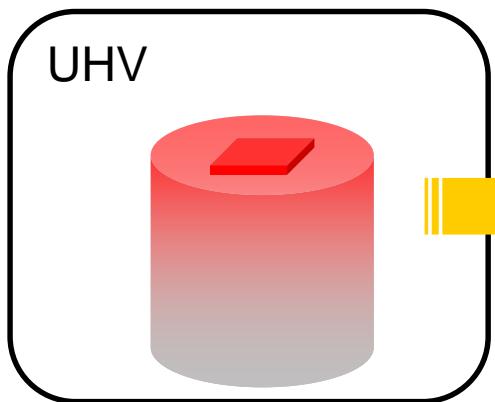
Increasing  $[\text{CO}_2]/[\text{SiH}_4]$  ratio leads to a decrease of both:

- **refractive index  $n$  and**
- **extinction coefficient  $\kappa$**
- **Bandgap: + 0.1 eV for  $[\text{CO}_2]/[\text{SiH}_4] = 2.5$**

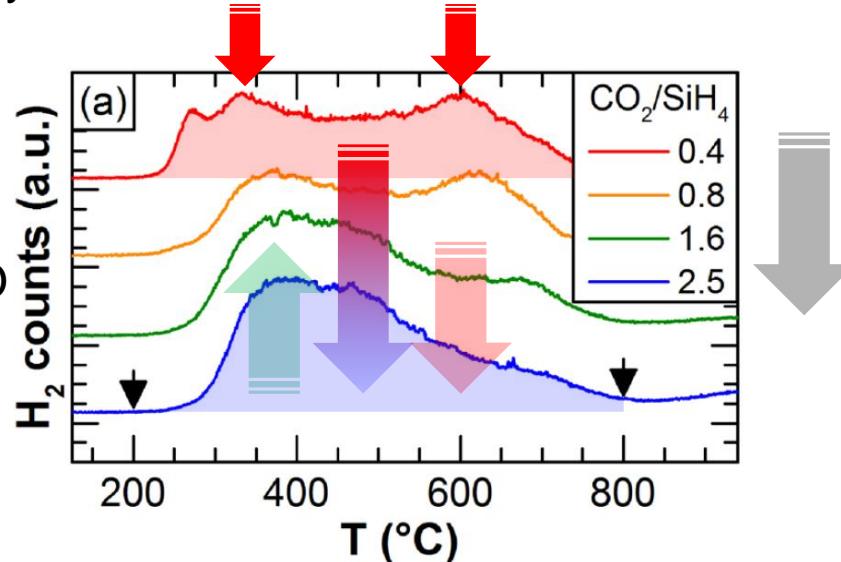
Linked to incorporation of hydrogen\* and oxygen

# a-SiO<sub>x</sub>:H: structural properties

- Thermal desorption spectroscopy to analyse the layer structure



H<sub>2</sub> ? H<sub>2</sub>O  
O<sub>2</sub>...



## What we observe:

- H<sub>2</sub> effusion spectrum varies  
high-T peak decreases, low-T peak  
increases with CO<sub>2</sub>/SiH<sub>4</sub>
- The area under the curves  
increases with CO<sub>2</sub>/SiH<sub>4</sub>



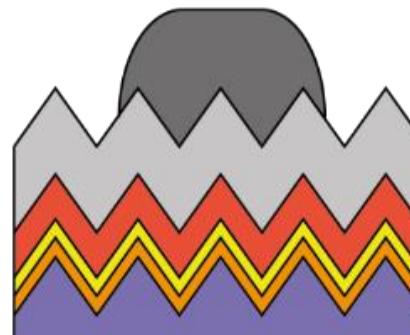
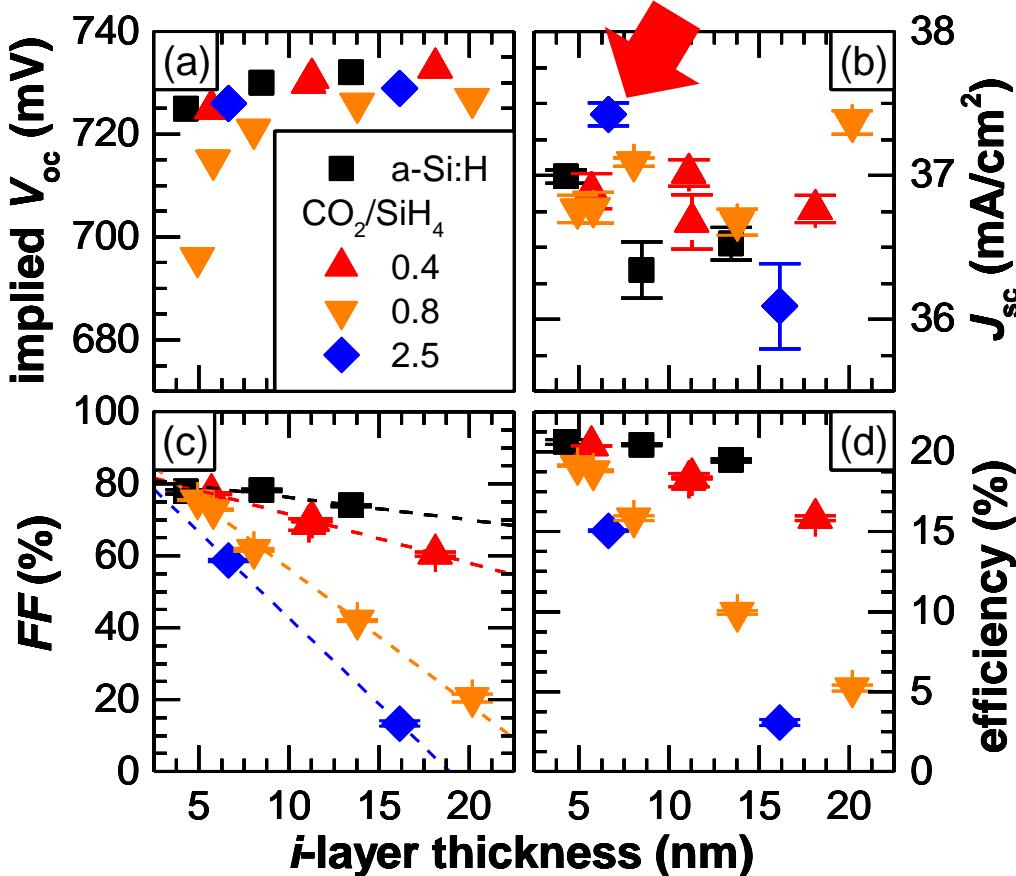
## What we learn:

- Structure gets increasingly porous  
with increasing CO<sub>2</sub>/SiH<sub>4</sub> ratio
- The amount of H<sub>2</sub> in the layer  
increases with CO<sub>2</sub>/SiH<sub>4</sub>



# a-SiO<sub>x</sub>:H: applied to hole contact

Variation in a-SiO<sub>x</sub>:H thickness  
with various [CO<sub>2</sub>]/[SiH<sub>4</sub>] ratios



**Good passivation:**  
Implied  $V_{oc}$ s between  
720–730 mV



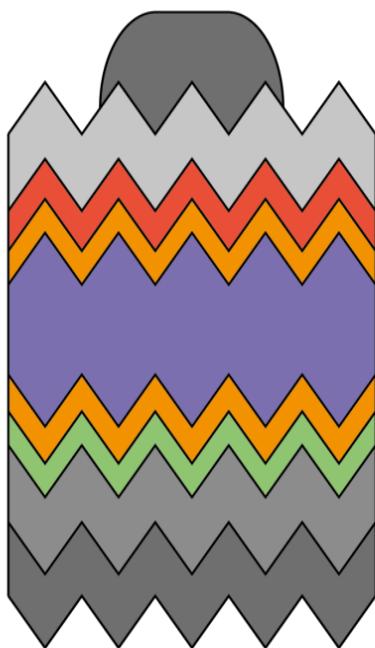
**Improved current:**  
by up to 0.4 mA/cm<sup>2</sup>  
(no clear trend with thickness  
due to reduced reflection)\*



**BUT drop in fill factor:**  
For a-SiO<sub>x</sub>:H cells, strongly  
influenced by [CO<sub>2</sub>]/[SiH<sub>4</sub>]  
ratio and thickness.



# a-SiO<sub>x</sub>:H permutations

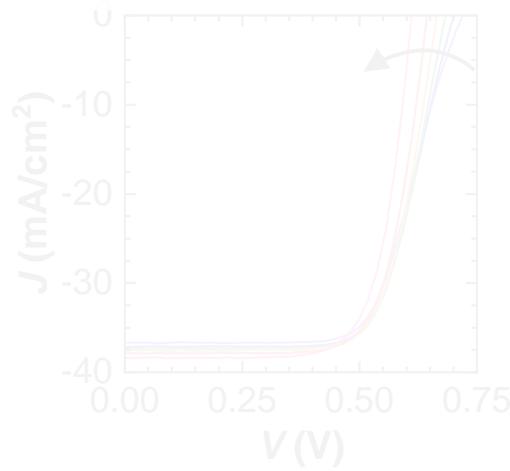
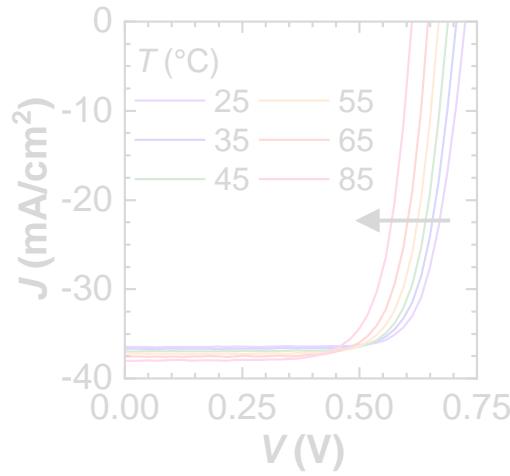
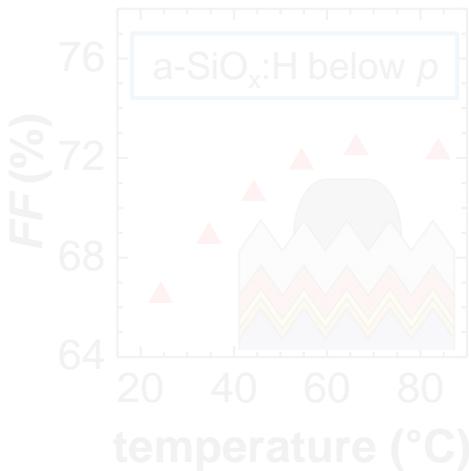
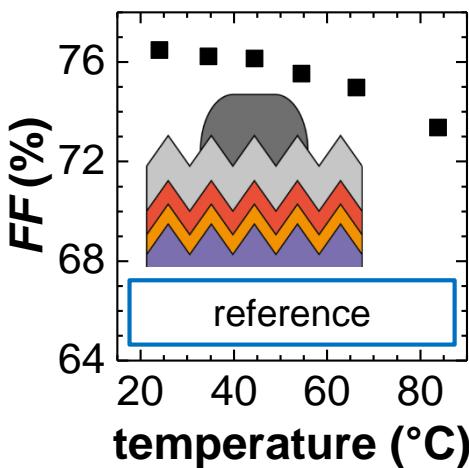


reference

a-SiO<sub>x</sub>:H below  $p$

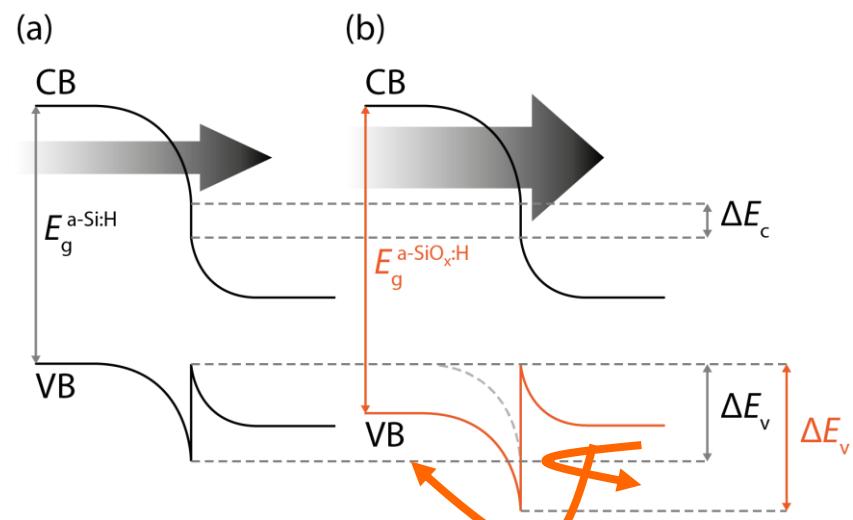
a-SiO<sub>x</sub>:H below  $n$

# Wide-bandgap a-SiO<sub>x</sub>:H: impact on FF

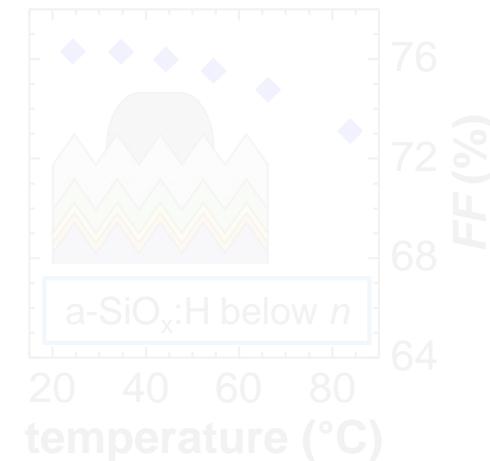
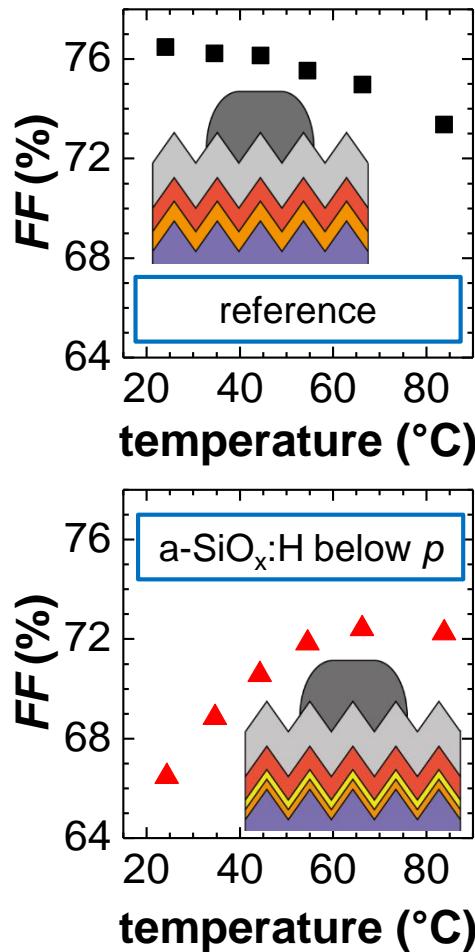


↓

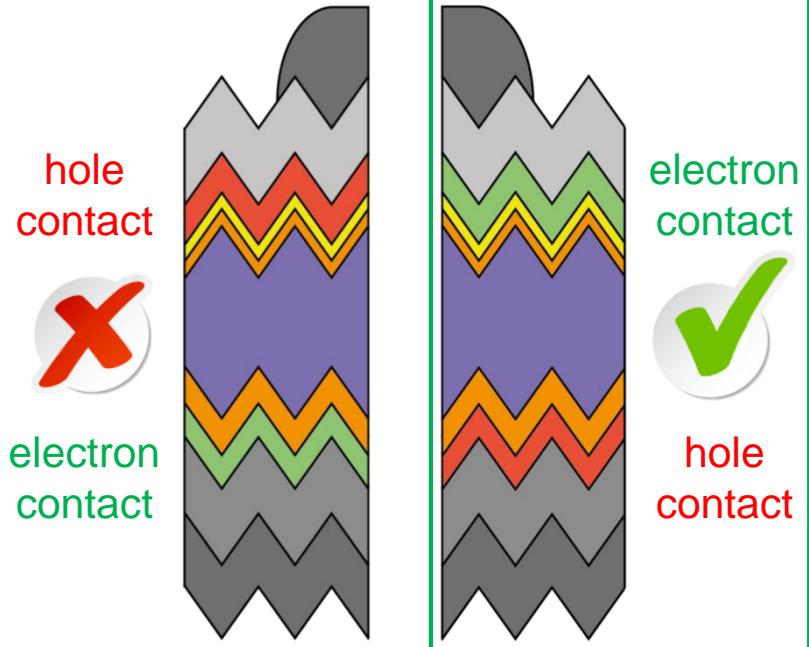
**Due to:**  
Transport problem  
associated with **increased**  
**valence band offset**  
(confirmed by simulation)



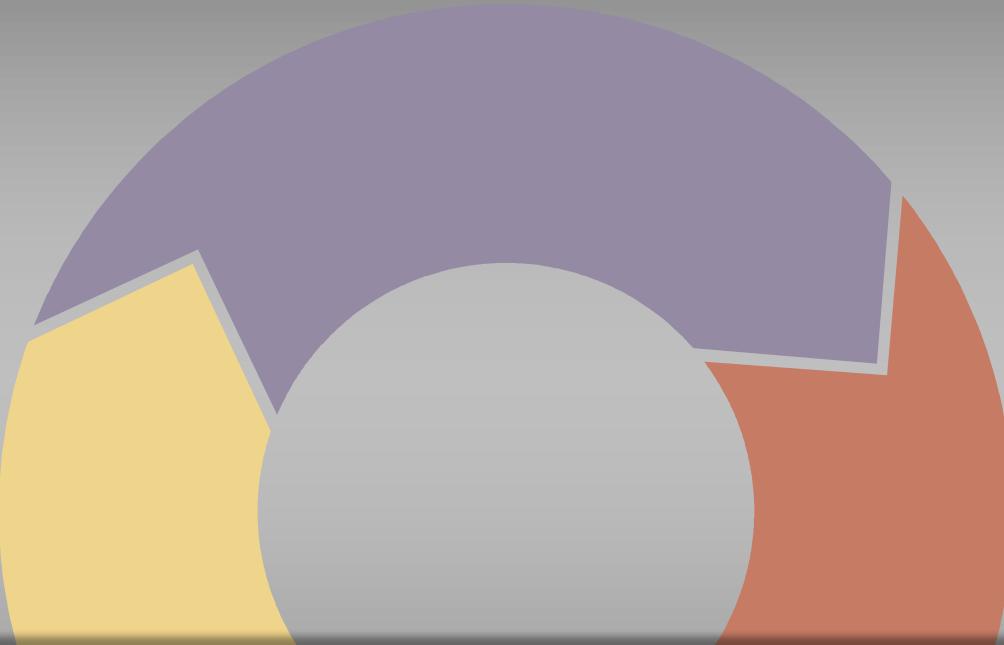
# Wide-bandgap a-SiO<sub>x</sub>:H: impact on FF



Confirmation that **holes** are the carriers that are affected most by the a-SiO<sub>x</sub>:H(*i*) layer



Potential gain in cells with hole collection at the rear

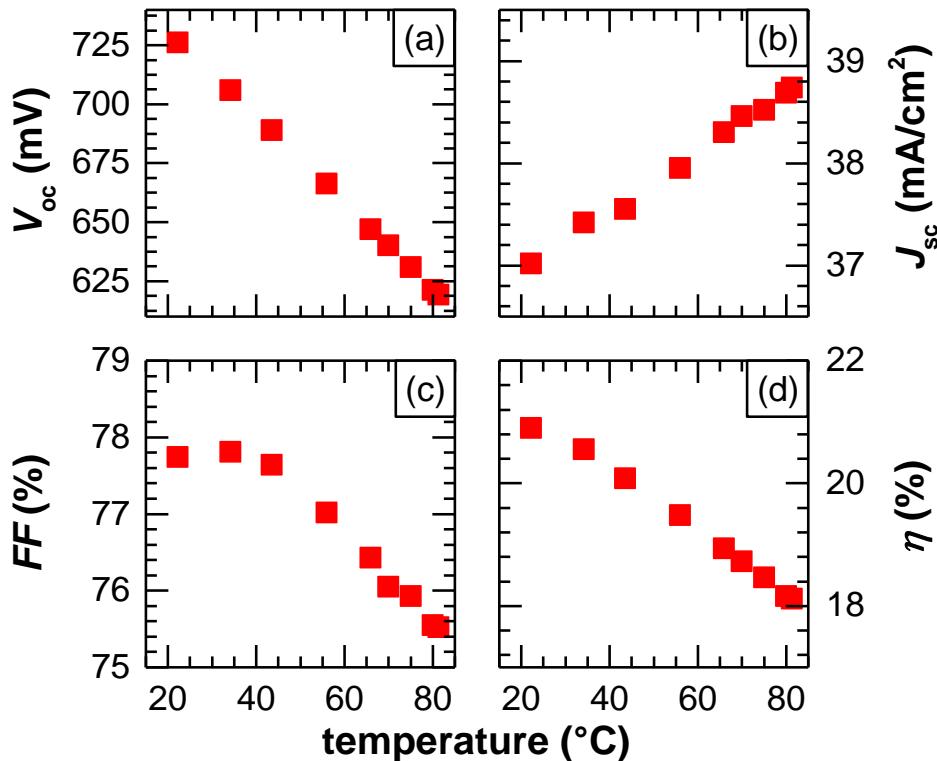


## **Temperature coefficients:**

*Ambient-temperature impact on lifetime & performance*

# Motivation

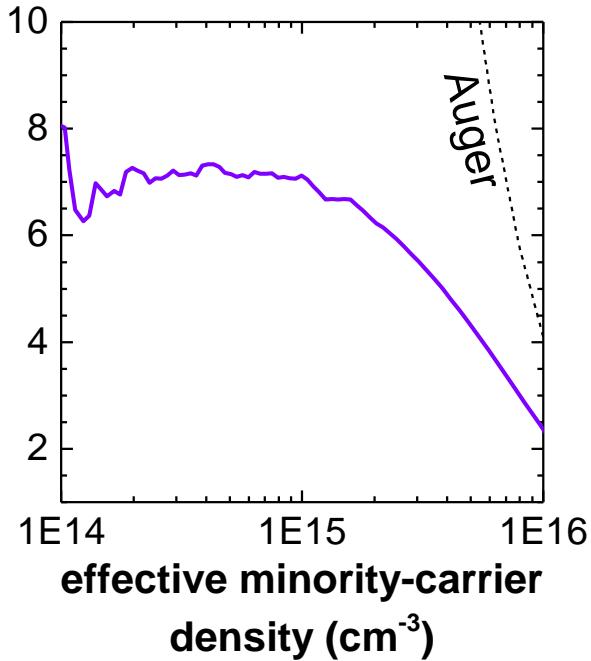
Typical temperature evolution  
of the cell parameters (SHJ solar cell)



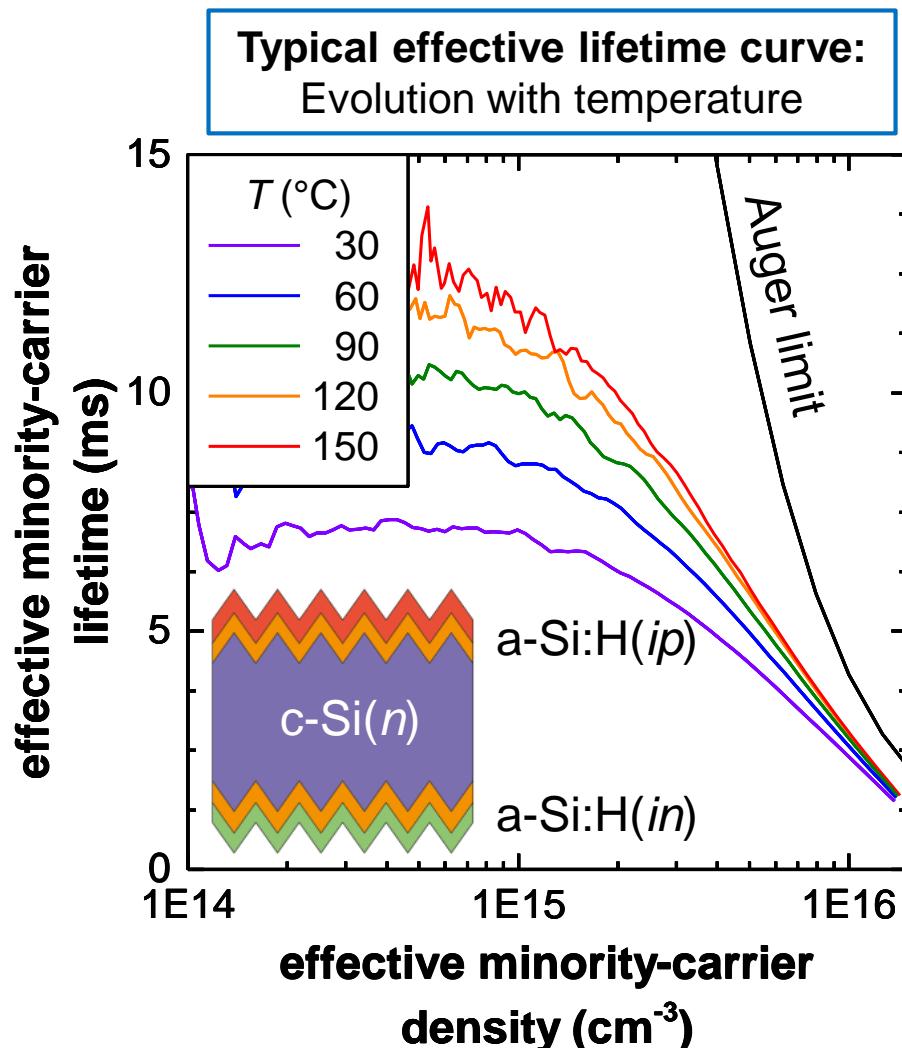
Temperature coefficients (TCs) important  
for operation in the field: cell  $T$  up to 90 °C



effective minority-carrier  
lifetime (ms)



# Lifetime( $T$ ) measurements: passivated wafers



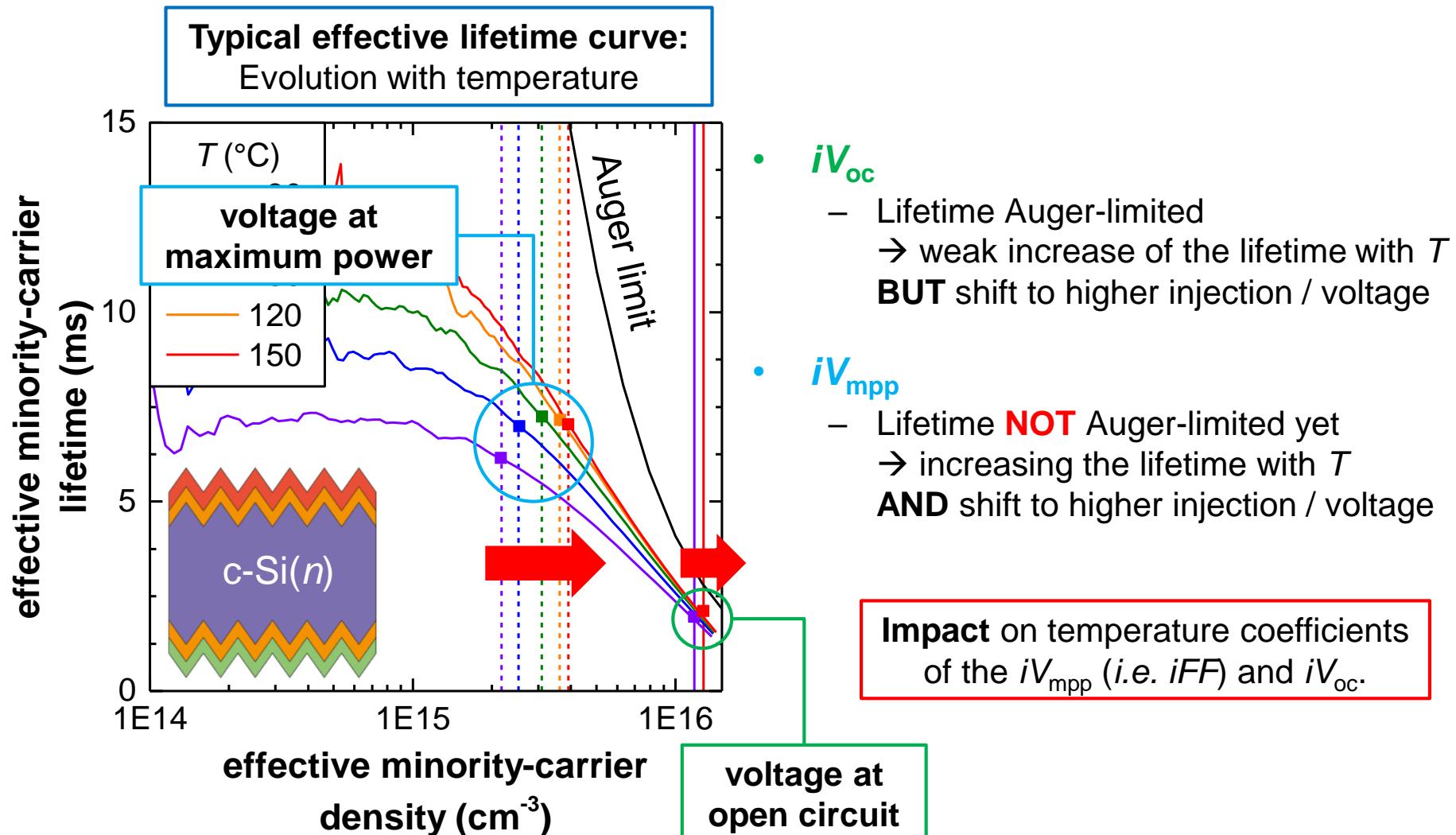
Possibly explained by change in  
**recombination statistics / capture**  
**cross-sections** with temperature

D. M. Goldie, American J. Material Science, 2013

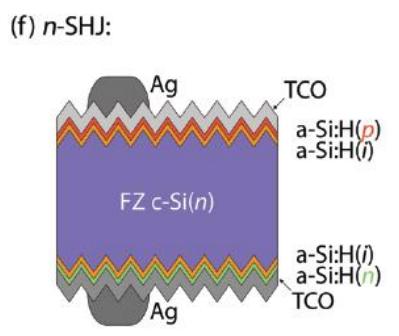
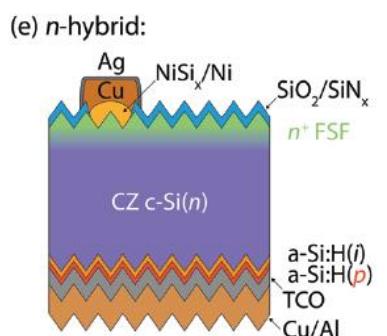
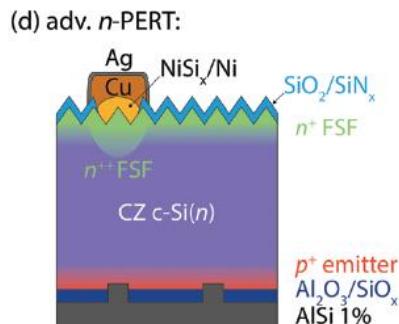
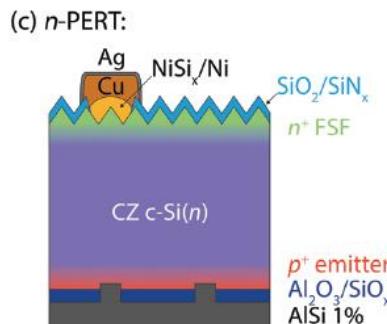
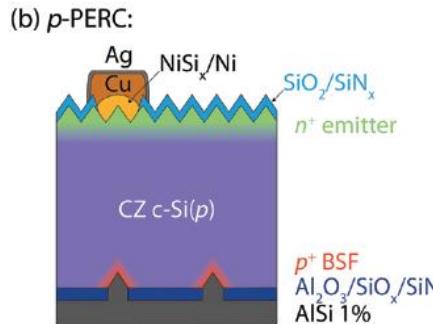
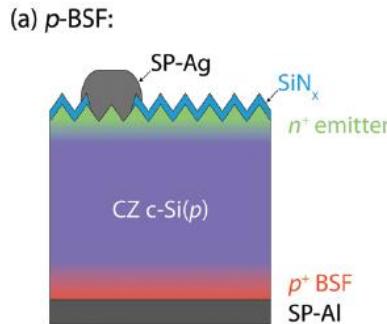


cell parameters ( $J_{\text{sc}}$ ,  $V_{\text{oc}}$ , FF)

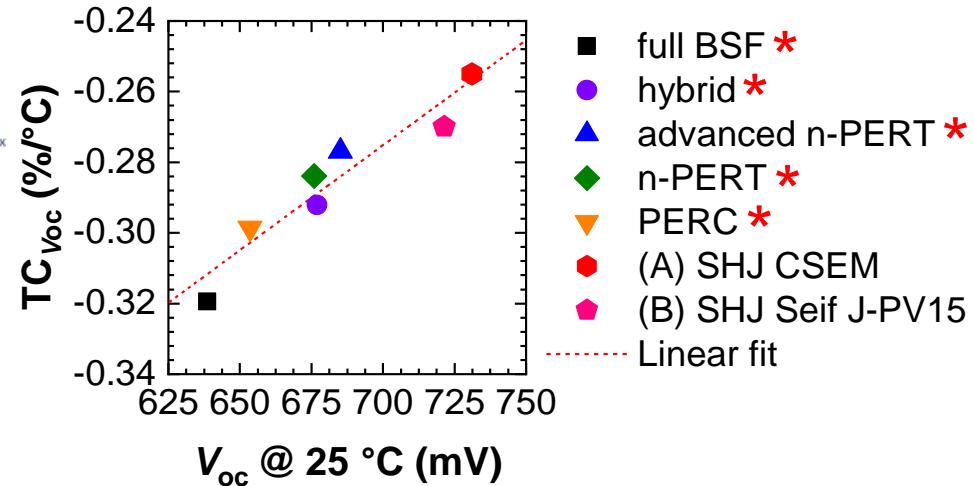
# Lifetime( $T$ ) measurements: passivated wafers



# Temperature coefficients (TC): *impact of $V_{oc}$*



\*Samples from:

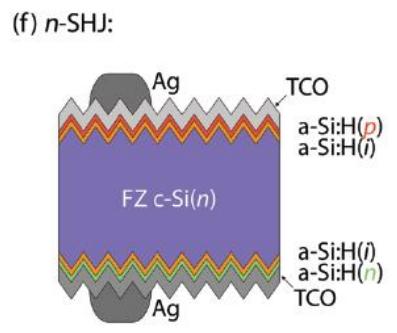
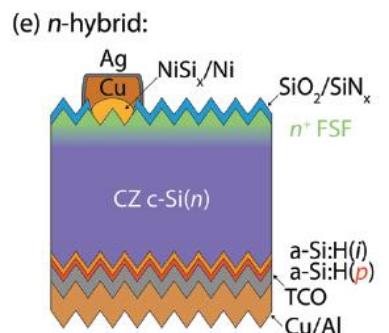
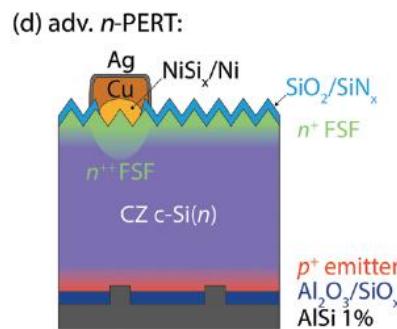
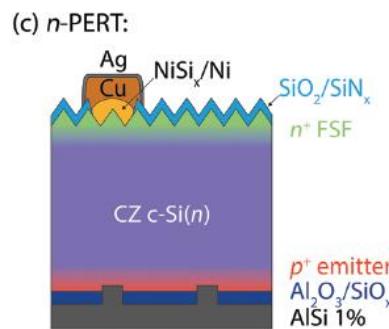
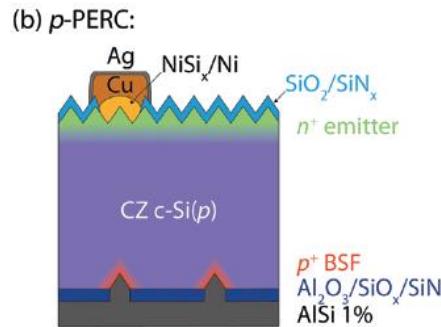
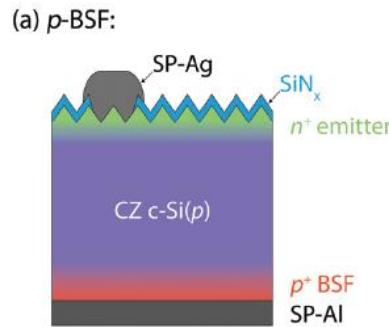


$$\frac{\partial V_{oc}}{\partial T} = -\frac{(V_{g0} - V_{oc} + \gamma kT/q)}{T}$$

M. A. Green, et al., *J. Appl. Phys.*, vol. 58, 1985.

**High-quality passivation (high  $V_{oc}$ )**  
crucial for good TCs and FF!

# Temperature coefficients (TC): Cells vs. Modules



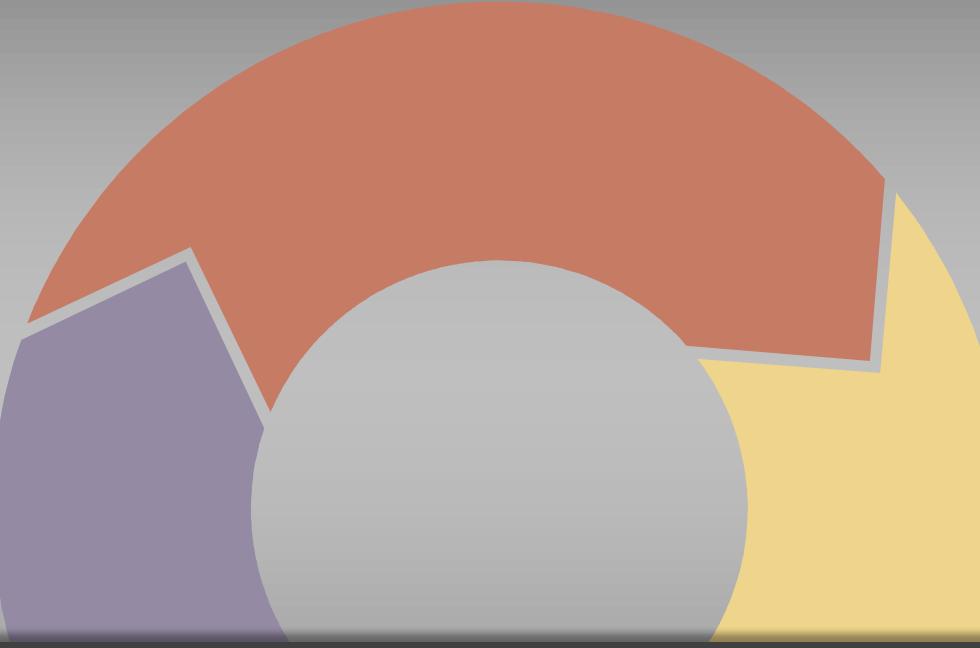
Study of temperature coefficients (TC) of different state-of-the-art cells and comparison to modules

- $\text{TC}_{\text{Voc}}$  and  $\text{TC}_{\text{Jsc}}$  are similar BUT  $\text{TC}_{\text{Vmpp}}$  is worse for modules

Additional series resistance induced by the interconnections between the cells in a module.

**High  $V_{\text{oc}}$  and low-resistive interconnections** are essential for hot and sunny climates.





## **Alternative transparent electrodes:**

*Atomic-layer-deposited ZnO:Al & Organic overlayers*

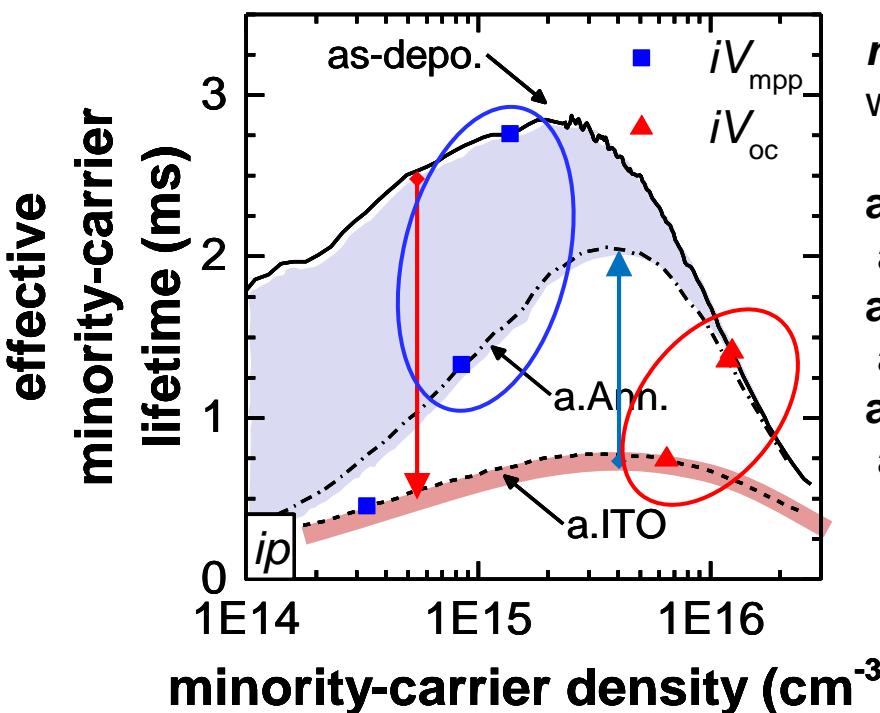
# Motivation

Thinner a-Si:H layers at the front

Higher current output (increased  $J_{sc}$ )

(Permanent) damage associated with sputtering possible

Degradation at lower injection: non-optimal TCO work function / field effect

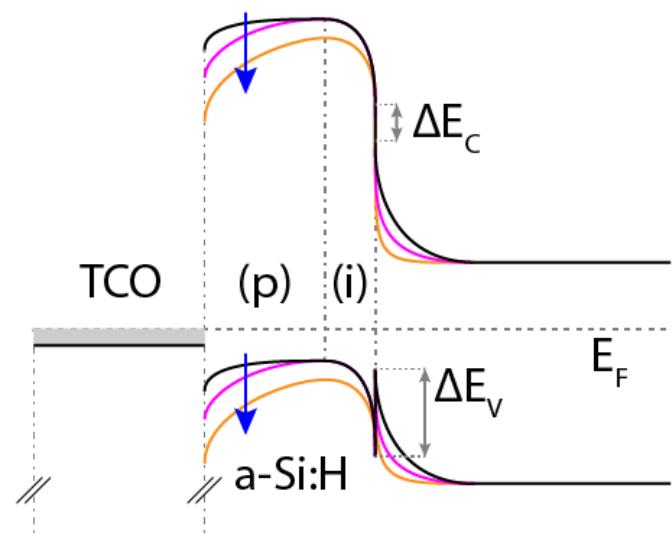


**n-type wafer**  
with *ip*/*ip*

**as-depo.:**  
after PECVD

**a.ITO:**  
after sputtering

**a.Ann.:**  
after annealing



**Solution:** Soft deposition technique or protective layer

**Solution:** TCO with an optimized work function

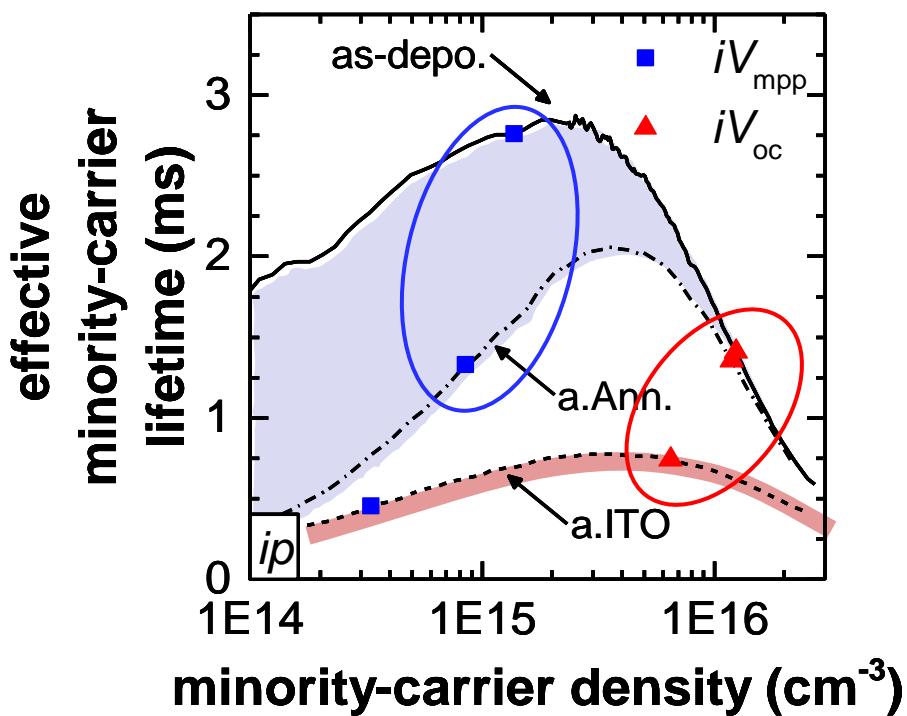
# Motivation

Thinner a-Si:H layers at the front

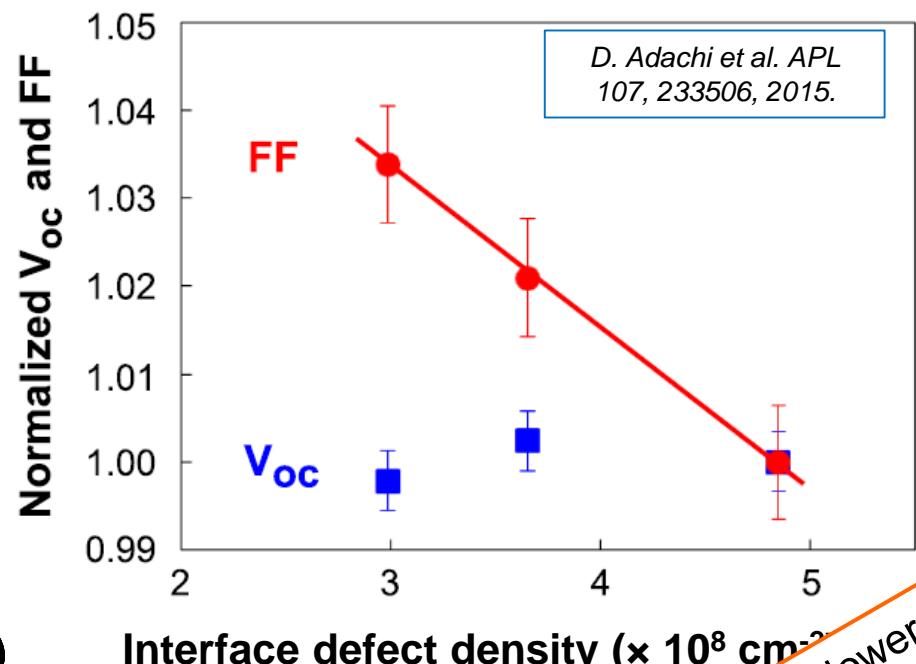
Higher current output (increased  $J_{sc}$ )

(Permanent) damage associated with sputtering possible

Degradation at lower injection: non-optimal TCO work function / field effect



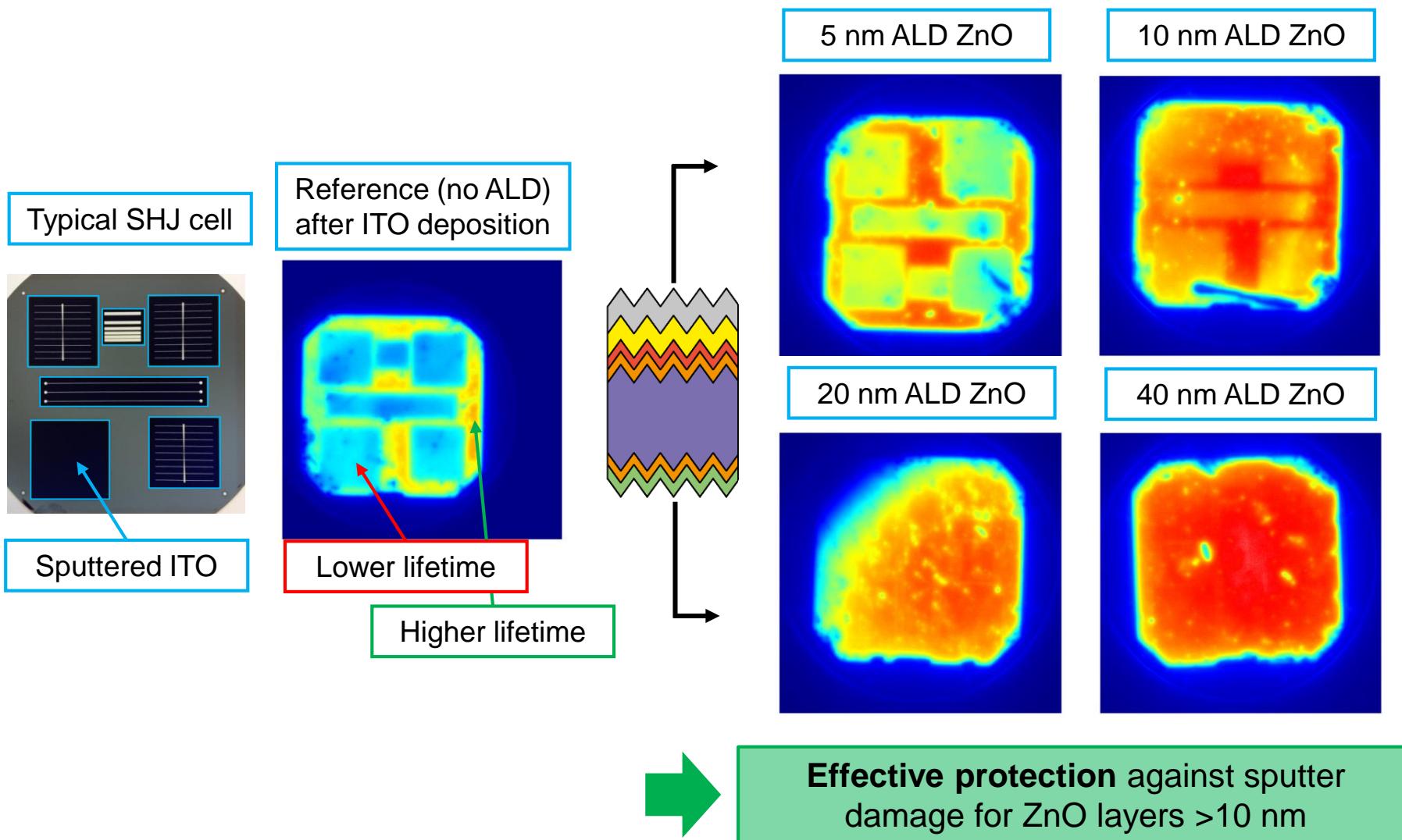
**Solution:** Soft deposition technique or protective layer



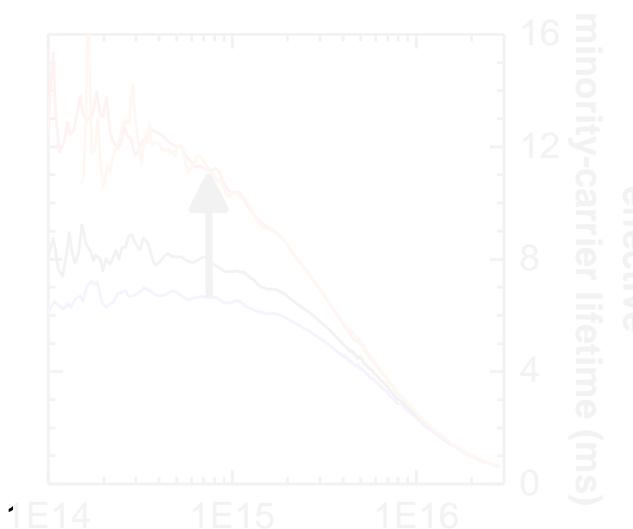
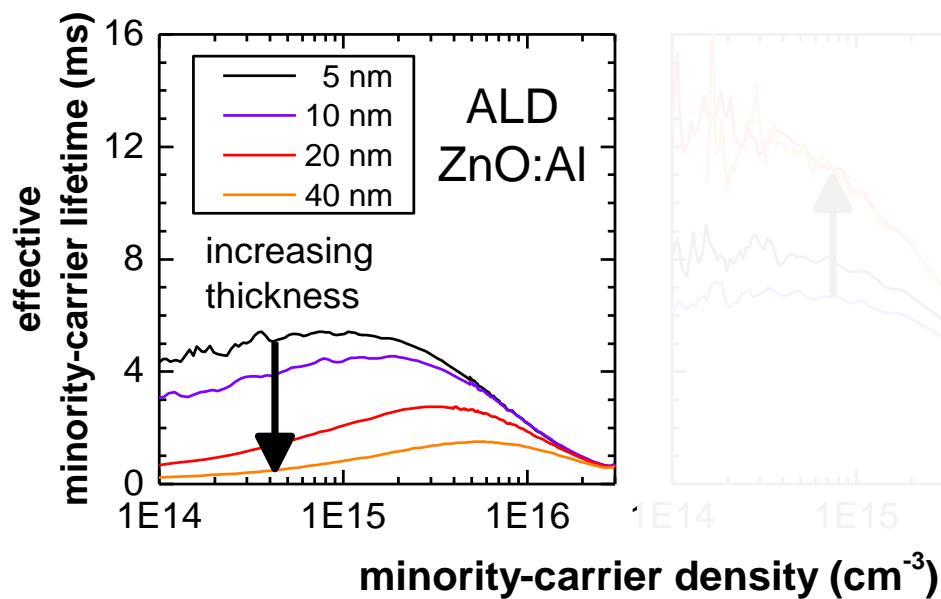
**Solution:** TCO with an optimized work function

+ lower defect density!

# ALD ZnO:Al layer vs. sputter-damage



# Lifetime variation: a workfunction effect



**Negative effect → lower  $iFF$**

**Solutions:** optimizing ZnO, applying different TCO or organic semiconductors.

**Positive effect → higher  $iFF$**

**Potential application on the electron-collecting side of the device**

**Work function engineering crucial for high  $FF$  values.**

# Alternative materials: Organic overlayers

$a\text{-Si:H}(p)$

$a\text{-Si:H}(n)$

$a\text{-Si:H}(i)$

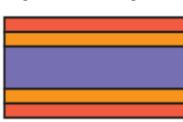
$c\text{-Si}(n)$

PVK

PECVD  
*in-sample*



*ip-sample*



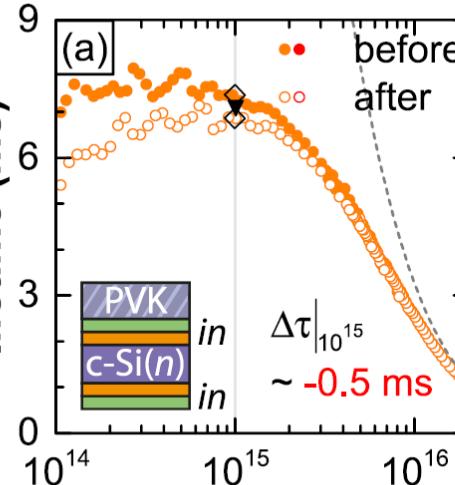
SPIN  
COATING



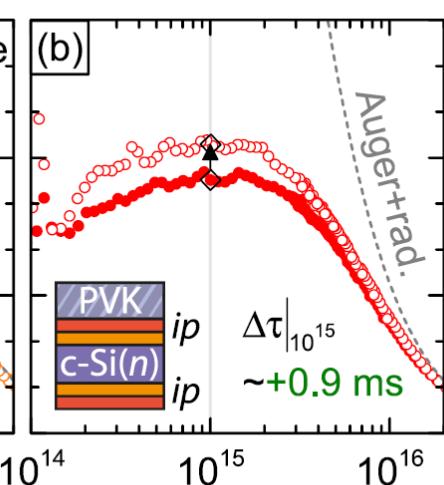
poly N-vinylcarbazole (PVK)

effective minority-carrier lifetime (ms)

*in-sample*



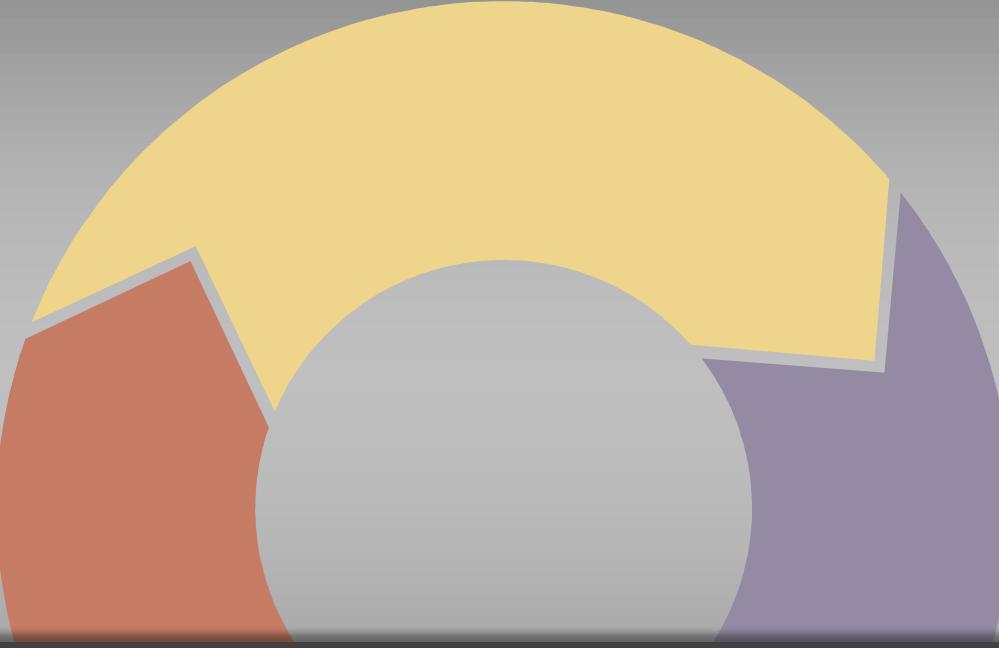
*ip-sample*



minority-carrier density ( $\text{cm}^{-3}$ )

Inverse effect on  
*in/in* (**NEGATIVE**) and  
*ip/ip* (**POSITIVE**)  
passivated samples.

Work function engineering:  
Tunable effect with variation  
of the PVK doping.



# Nanocrystalline layers

*For silicon heterojunction solar cells*

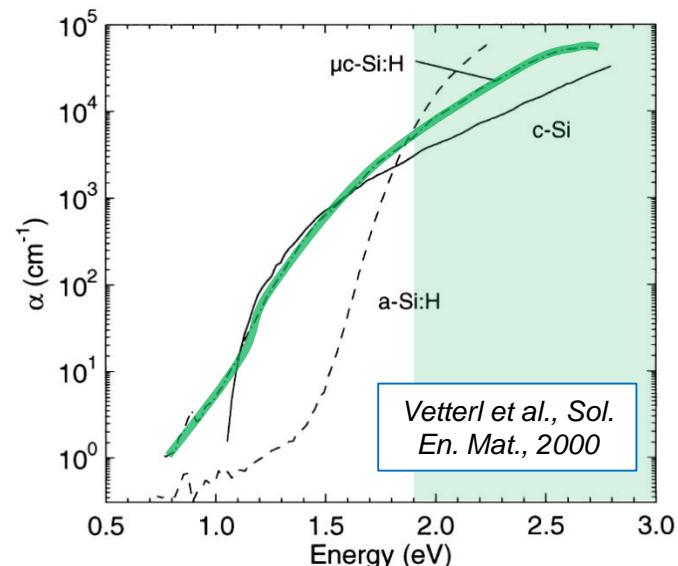
# Motivation

## Benefits of nanocrystalline materials

- **Optically:** *indirect bandgap of c-Si*
  - better response at short wavelengths
- **Electrically:** *higher doping efficiency and improved transport properties*
  - suppression of Schottky barriers  
→ improved contact resistivity

## Requirements for PECVD nc-Si layers

1. **Fast nucleation** (thicknesses  $\sim$ 10–20 nm)
2. **Sufficiently high crystallinity**
3. **'Soft' deposition for pristine passivation**



# Strategies for nanocrystalline layers

method	layer crystallinity/ nucleation speed	application in devices
CO <sub>2</sub> plasma treatments	✓	✗
a-SiO <sub>x</sub> :H buffer layers	✓ ✓	✗ ✗
SiF <sub>4</sub> nucleation layers	✓ ✓	✓
SiH <sub>4</sub> → Si <sub>2</sub> H <sub>6</sub>	✓	✓
H <sub>2</sub> → D <sub>2</sub>	✓	✓
Temperature	✓ ✓	✓
✗ Higher deposition frequency (VHF)	✓ ✓ ✓	✓
→ Low frequency and higher pressure	✓ ✓	✓ ✓

# nc-Si:H(*n* or *p*): device results

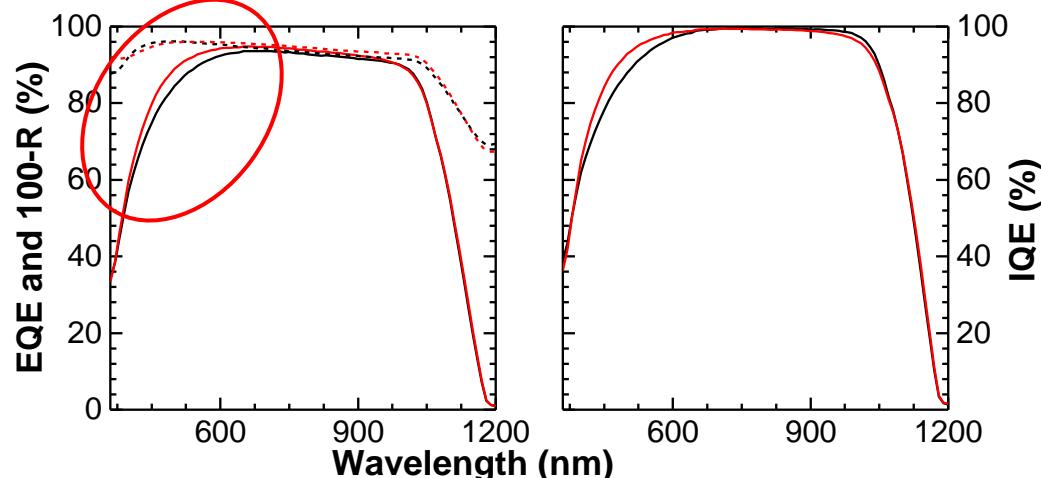
nc-Si:H(*n*) or nc-Si:H(*p*) layers implemented into SHJ devices

[reference values]

Deposition regime	nc-Si:H(X)	position	$V_{oc}$ (mV)	$J_{sc}$ (mA/cm <sup>2</sup> )	FF (%)	$\eta$ (%)
81.36 MHz (2 mbar)	<i>p</i>	front	717 [719]	37.7 [36.8]	72.6 [72.7]	19.6 [19.2]
13.56 MHz ( $SiF_4$ ), 40.68 MHz (> 2 mbar)	$i_{SiF_4}$ (nucl.)	front	718 [718]	36.0 [37.1]	78.4 [76.7]	20.3 [20.4]
13.56 MHz (> 2 mbar)	<i>p</i>	rear	720	36.5	79.2	20.8
	<i>n</i>	front	719	37.0	78.7	20.9

## All cells

Textured, 1-5 Ωcm, nominal 240 μm, *n*-type FZ, 2 × 2 cm<sup>2</sup>, with screen-printed Ag front contacts and full Ag contact at the rear.



# nc-Si:H(*n* or *p*): device results



**Gain in  $J_{sc}$**   
up to  $\sim 1 \text{ mA/cm}^2$



**Gain in  $FF$**   
up to 2% (abs.)

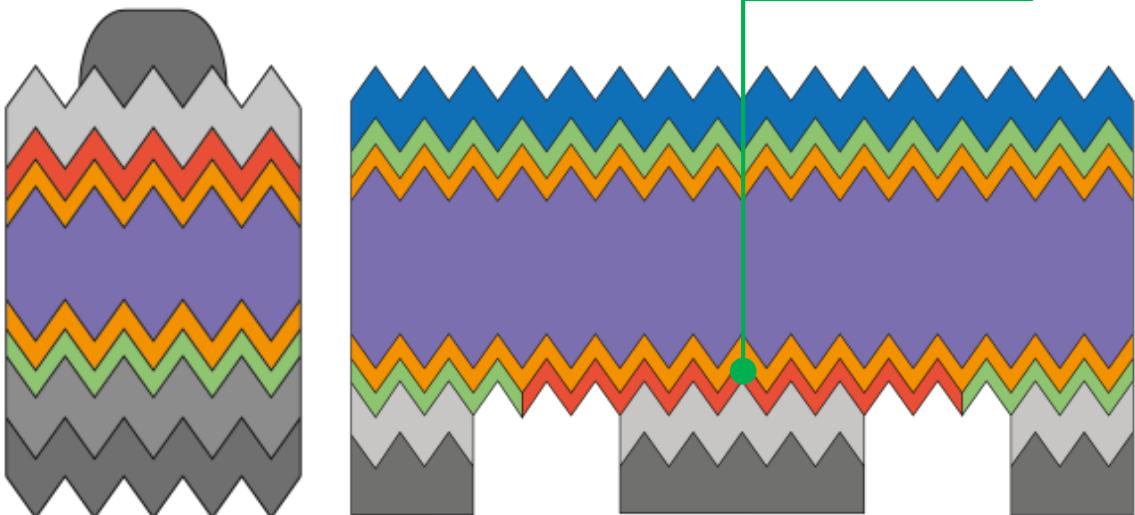
**Stable  $V_{oc}$  values**  
of  $\sim 720 \text{ mV}$

**Conversion efficiencies**  
up to 20.9%

## Requirements

1. Fast nucleation
2. High crystallinity
3. 'Soft' deposition

Achieved with **simple, industry-compatible process** using **standard gases**.

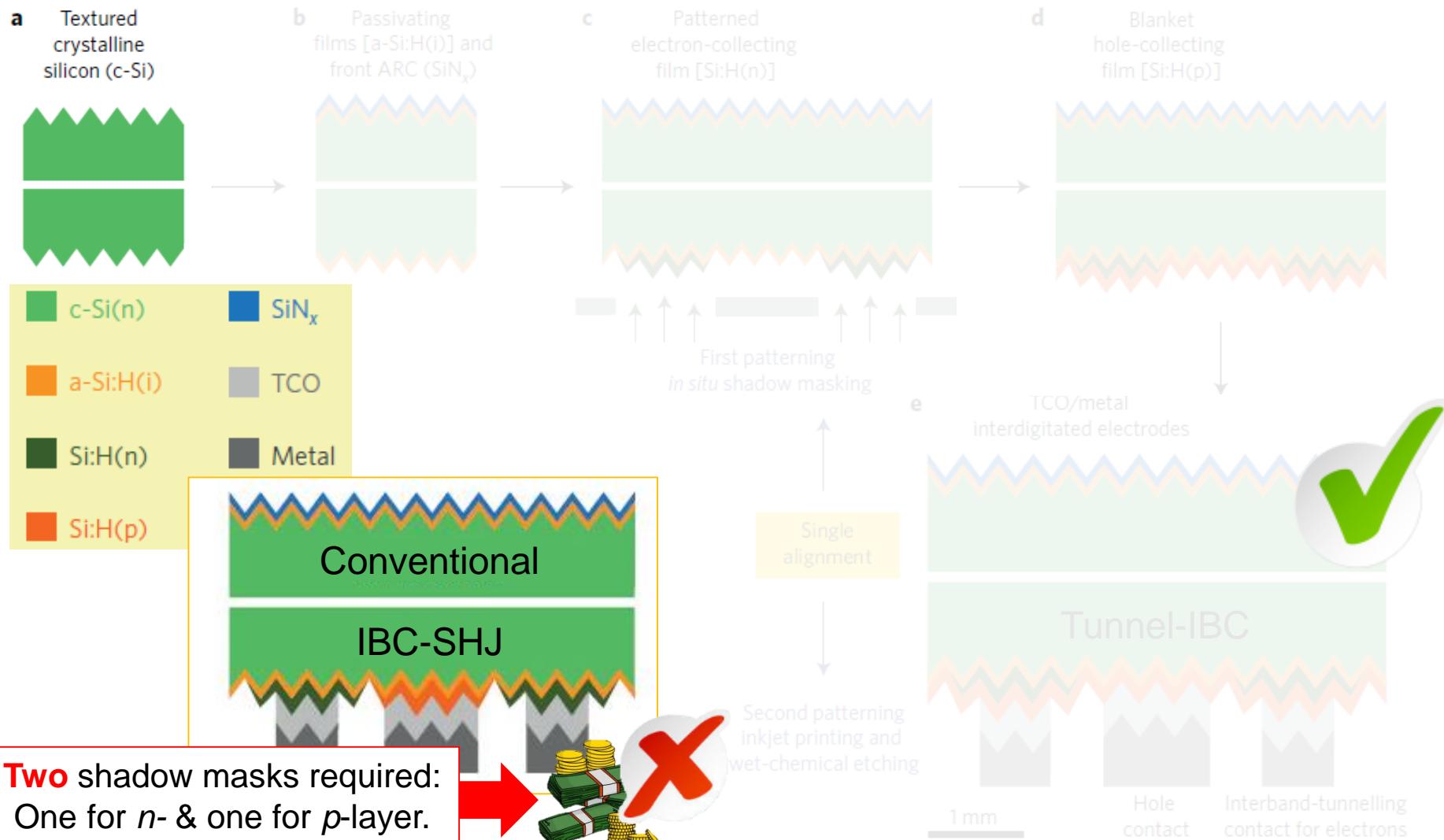


**Readily applicable** without additional costs.

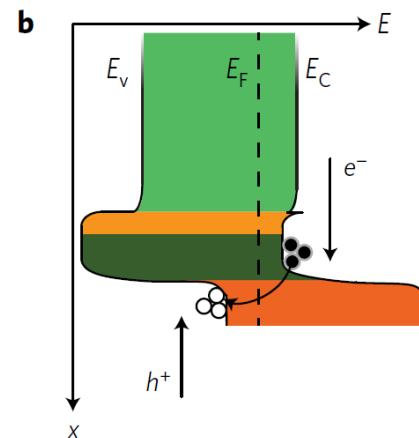
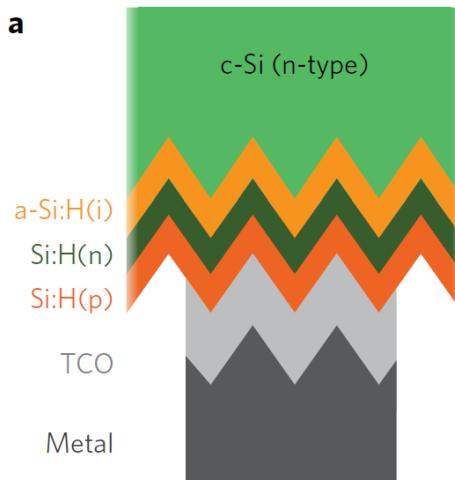
**Standard 2-side-contacted SHJ (full area)**

**Rear-contacted SHJ (reduced contacting area)**

# Rear-contacted cells: nc-Si:H(*n* and *p*) inside

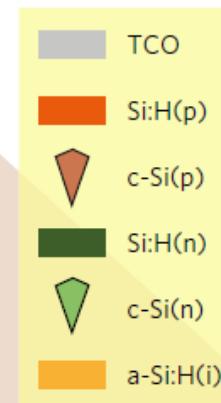
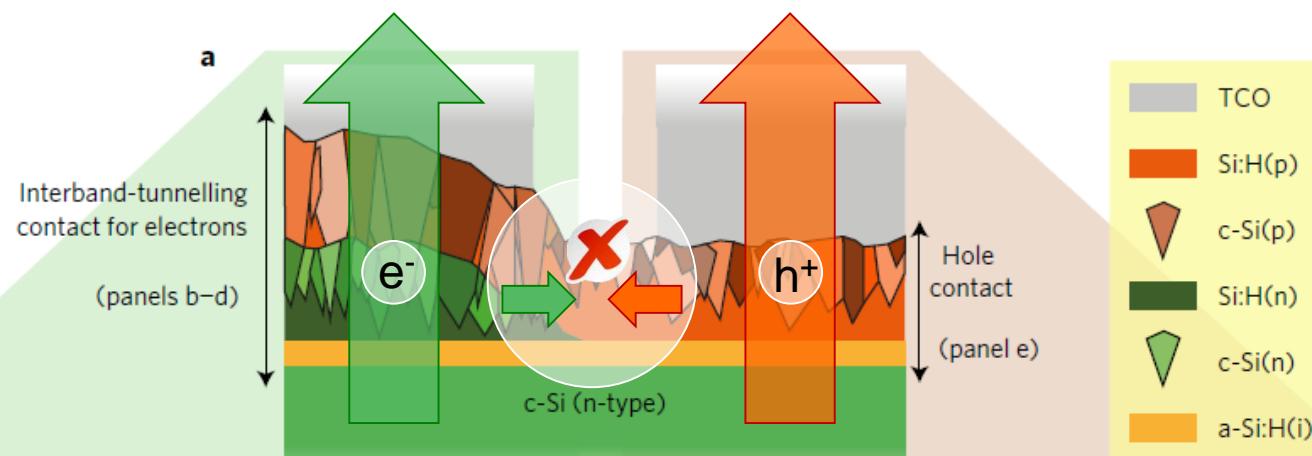


# Rear-contacted cells: nc-Si:H(*n* and *p*) inside

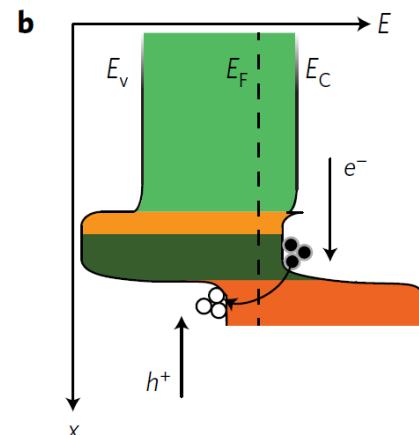
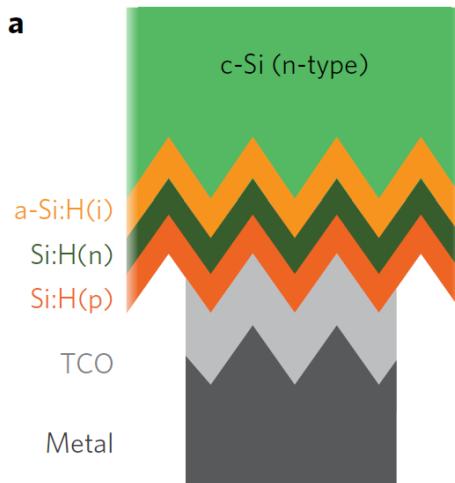


- Efficient interband-tunneling contact for electrons.
- Minimized resistive losses (nc-Si) and optimal carrier selectivity ( $e^-$ )
- Low lateral conductance to prevent shunts, thanks to **grain boundaries** and **incubation layer**

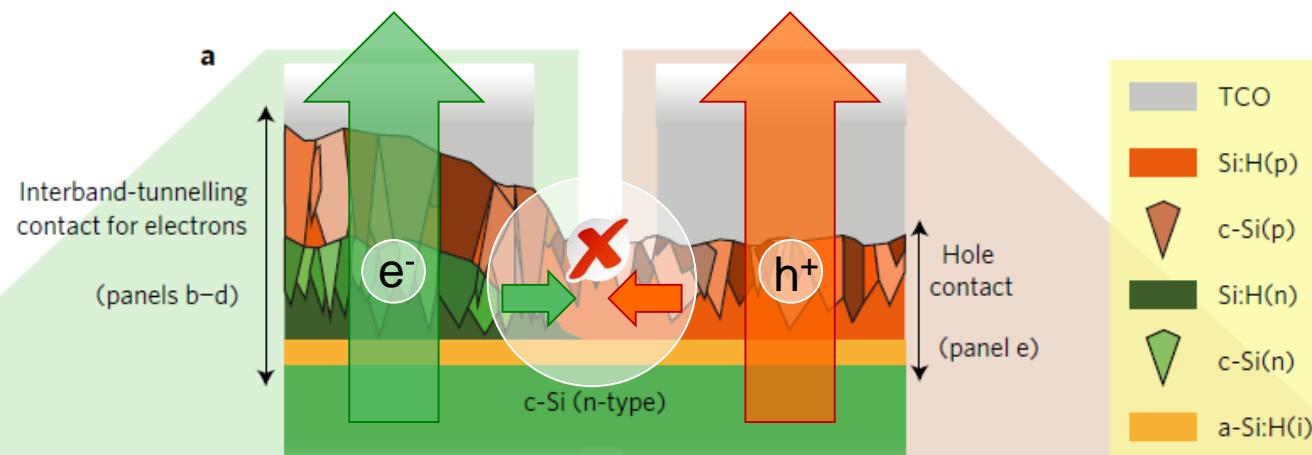
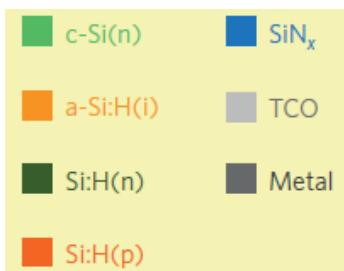
c-Si(n)	SiN <sub>x</sub>
a-Si:H(i)	TCO
Si:H(n)	Metal
Si:H(p)	



# Rear-contacted cells: nc-Si:H(*n* and *p*) inside



**Certified efficiency**  
Area = 9.00 cm<sup>2</sup> (da)  
 $J_{SC} = 40.65 \text{ mA.cm}^{-2}$   
 $V_{OC} = 728.49 \text{ mV}$   
 $FF = 76.36\%$   
 **$\eta = 22.61\%$**



# Conclusions

## Ambient-temperature impact

- increasing lifetime with temperature
- $T_{C_{Voc}}$  depends on  $V_{oc}$ , device structure and materials
- Modules need high  $V_{oc}$ s and low-resistive cell interconnections

## Wide-bandgap oxides

Electrons may, but  
**holes should not** be collected  
through the window-layer

→ rear hole collection

→ gain in  $J_{sc}$  w/o losses in  $FF$   
+ 0.4 mA/cm<sup>2</sup> shown

## Alternative transparent electrodes

Atomic-layer-deposited ZnO:Al

- for effective sputter-damage protection and promising electron-collecting layer

→ potential gain in  $J_{sc}$  and  $FF$

## Alternative transparent electrodes

Organic overlayers

- work function engineering for improved contacts

→ potential gain in  $FF$

Nanocrystalline layers can help improve  
both optical and electrical device performance

→ gain in  $J_{sc}$  and  $FF$   
+1 mA/cm<sup>2</sup> and +2% shown





## Passivating contacts with Transition Metal Oxides (TMO) deposited by PECVD

### Why PECVD?

- Common in industry
- High throughput
- Wider parameter space (temperature, pressure, gas ratios,...)
- Possibility to use other precursor gases (vary growth mode and material properties)



Partners:

MEYER BURGER

SUNRISE GLOBAL SOLAR ENERGY

Johannes P. Seif, Anh Le, and Ziv Hameiri

### Why TMOs?

- Relatively wide band gaps, yet small conduction and valence band offsets
- Promising materials for electron- (e.g.  $\text{TiO}_x$ ) and hole-collection (e.g.  $\text{WO}_x$ )
- Fixed charges for passivation

### State-of-the-art deposition for TMOs

- Atomic Layer Deposition
- Sputtering

Our approach  
**PECVD**

### Challenges?

- Uniformity of thin layers
- Thermal stability
- Additional passivation layer needed?



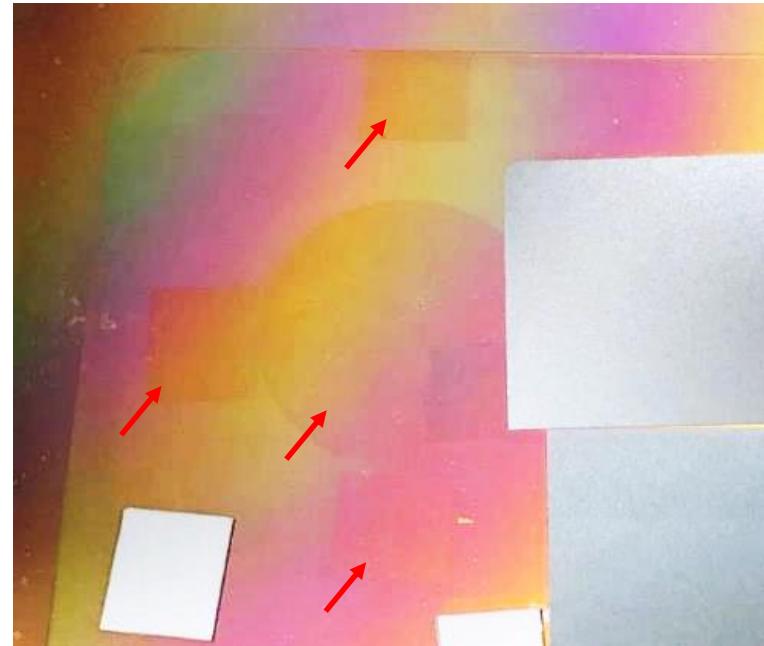


**UNSW**  
SYDNEY

Australia's  
Global  
University

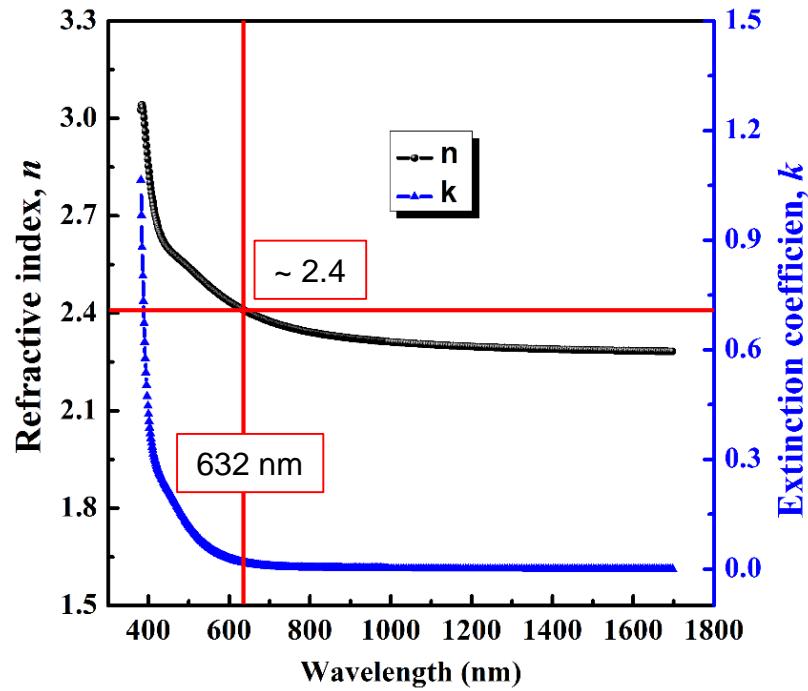
## Modifications of the AK-800

Delivery of new precursors  
and first  $\text{TiO}_x$  depositions



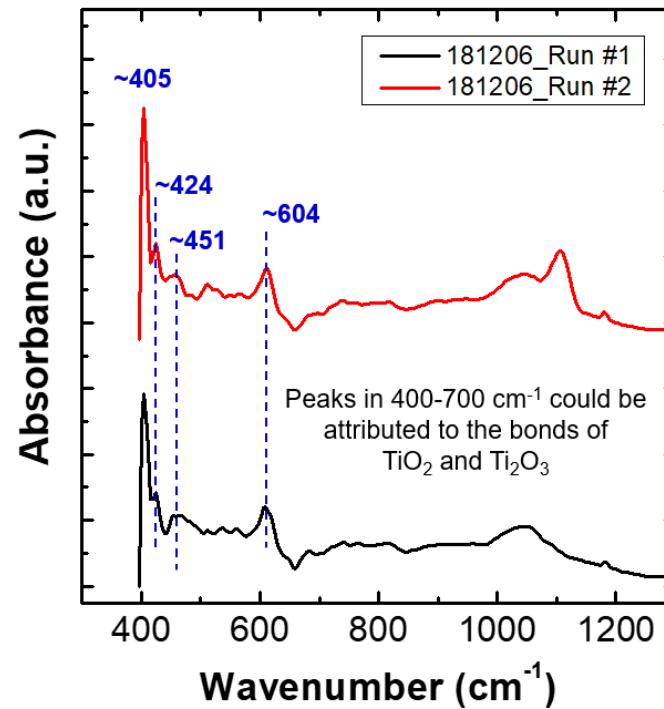
# TMO depositions: *First results*

Spectroscopic Ellipsometry



**Thickness:** 7.2 nm  
**Refractive index:** 2.4 @ 632 nm

Fourier-Transform Infrared Spectroscopy (FTIR)





Australia's  
Global  
University

**Other ongoing projects:**  
With national (incl. UNSW) and  
international partners

- **Metal work function impact on recombination**  
(ANU and KAUST)
- **Temperature dependence on cell performance**  
(KAUST)
- **Hydrogen migration in c-Si wafers**  
(UNSW, Phill Hamer)
- **Defect parameters of passivated interfaces**  
(UNSW, Michelle Vaqueiro Contreras)
- **Cell perimeter recombination**  
(UNSW)



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# Thank you for your attention!